

HC05

MC68HC05F4
MC68HC705F4

TECHNICAL
DATA



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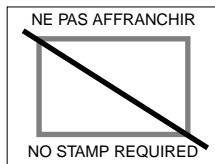
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**MC68HC05F4
MC68HC705F4**

**High-density complementary
metal oxide semiconductor
(HCMOS) microcontroller unit**

Conventions

Where abbreviations are used in the text, an explanation can be found in the glossary, at the back of this manual. Register and bit mnemonics are defined in the paragraphs describing them.

An overbar is used to designate an active-low signal, eg: $\overline{\text{RESET}}$.

Unless otherwise stated, shaded cells in a register diagram indicate that the bit is either unused or reserved; 'u' is used to indicate an undefined state (on reset).

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1

INTRODUCTION

The MC68HC05F4 is a member of the M68HC05 family of HCMOS microcomputers. In addition to 4K bytes of ROM, the MC68HC05F4 contains 256 bytes of RAM and 256 bytes of EEPROM. The on-board features of this device make it particularly suited to highly integrated and cost effective telephone handsets. The timer and DTMF generator allow for both pulse and tone dialling; in addition to telephone set-up parameters and features such as last number redial, the EEPROM can typically store up to 12 telephone numbers of 20 digits, even after power has been removed from the circuit; the keyboard interrupt facility permits a direct interface to a telephone keypad. In addition to the high level of integration achieved, careful attention has also been paid to the low-power and low-voltage performance of the MC68HC05F4, which is of major importance in many telecommunications applications.

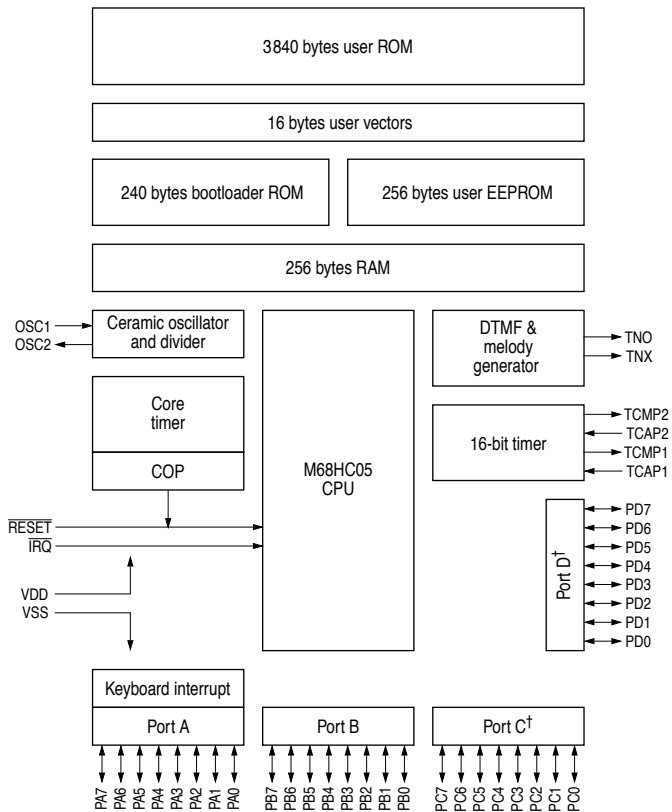
The MC68HC705F4 is an EPROM version of the MC68HC05F4, with the User ROM replaced by 8kbytes of EPROM. All references to the MC68HC05F4 apply equally to the MC68HC705F4, unless otherwise noted.

1.1 Features

- Fully static design featuring the industry-standard M68HC05 CPU core
- 3840 bytes of user ROM, plus 16 bytes for vectors
- 256 bytes of RAM
- 256 bytes of user EEPROM
- DTMF/melody generator
- 16-bit programmable timer with two input captures and two output compares
- 15 stage multipurpose core timer with timer overflow, real time interrupt and COP watchdog
- COP watchdog timer (mask option)
- Power saving STOP and WAIT modes
- I/O lines (8 with high-voltage, open-drain outputs)
 - 44 QFP configuration – total of 32 dedicated bidirectional I/O pins
 - 28 SOIC/PDIP configuration – total of 16 dedicated bidirectional I/O pins
- Keyboard interrupt facility on eight of the I/O lines
- Hardware interrupt with edge or edge-and-level sensitive interrupt trigger
- On-chip oscillator
- On-chip low voltage detection circuit
- Two selectable bus frequencies
- Power-on and power-off resets; low voltage detection circuitry (EEPROM)
- Available in 44-pin QFP package, 28-pin SOIC package and 28-pin PDIP package (ports C and D not available in 28-pin packages)

1.2 Mask options for the MC68HC05F4

There are three mask options available on the MC68HC05F4: STOP instruction – enable/disable, low voltage reset – enable/disable, and COP watchdog timer – enable/disable. These options are programmed during fabrication and must be specified by the customer at the time of ordering.



† Note that ports C and D are only available with the 44-pin package.

Figure 1-1 MC68HC05F4 block diagram



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MODES OF OPERATION AND PIN DESCRIPTIONS

The normal operating mode of the MC68HC05F4 is single chip mode. There is also a bootloader mode, primarily for factory test purposes. In addition to these modes, there are three low power modes which may be entered and exited at will from user mode: STOP, WAIT and data retention.

2.1 Single-chip mode

This is the normal user operating mode, in which the device functions as a self-contained microcomputer unit, with all on-board peripherals and I/O ports available to the user. All address and data activity occurs within the MCU.

2.2 Low power modes

2.2.1 STOP mode

The STOP instruction places the MCU in its lowest power consumption mode. In STOP mode, the internal oscillator is turned off, halting all internal processing, including timer (and COP watchdog timer) operation.

During STOP mode, the core timer interrupt flags (CTOF and RTIF) and interrupt enable bits (TOFE and RTIE) in the CTCSR, as well as the 16-bit timer flags in register TSR and interrupt enable bits in register TCR, are cleared by internal hardware. The I-bit in the CCR is cleared to enable external interrupts. All other registers, the remaining bits in the CTCSR, and memory contents remain unaltered. All input/output lines remain unchanged. The processor can be brought out of STOP mode only by an interrupt ($\overline{\text{IRQ}}$, Keyboard, LVI) if enabled or $\overline{\text{RESET}}$ (external reset or low voltage reset – LVR). See [Figure 2-1](#).

The STOP instruction can be disabled by a mask option. When disabled, the STOP instruction is executed as a NOP.

2.2.2 WAIT mode

The WAIT instruction places the MCU in a low power consumption mode, though it consumes more power than in STOP mode. All CPU action is suspended, but the core timer and the 16-bit timer remain active. An interrupt from the core timer, 16-bit timer, \overline{IRQ} , keyboard, LVI, if enabled, will cause the MCU to exit the WAIT mode. An external reset, or LVR, causes the MCU to exit the wait mode.

During WAIT mode, the I-bit in the CCR is cleared to enable interrupts. All other registers, memory and input/output lines remain in their previous state. The DMG is still active during WAIT mode. See [Figure 2-1](#).

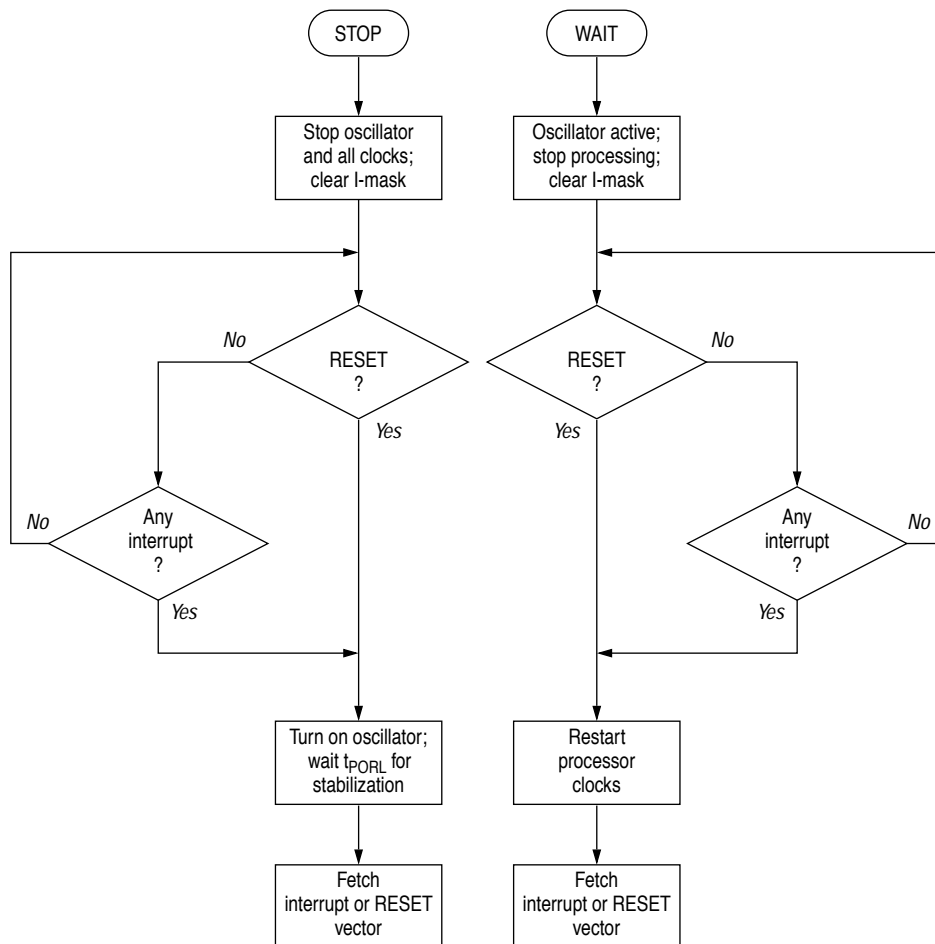


Figure 2-1 STOP and WAIT flowcharts

2.3 System options register

The MC68HC05F4 MCU contains a system options register which is located at address \$11. This register is used to control the LVI and the clock system.

Note: The LVI uses the voltage reference of the low voltage reset (LVR) circuitry. This means that the LVI can only be used if the LVR is enabled by mask option.

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
System options register (SOR)	\$0011	LVIF	LVIE	LVION	SC	IRQ	0	0	0	0000 0000

LVIF — Low voltage interrupt flag

- 1 (set) — A low voltage interrupt has occurred.
- 0 (clear) — No low voltage interrupt has occurred.

LVIF is a read only status bit and is set by the low voltage detection circuit, if power supply VDD falls below V_{Lvi} , provided the LVR is enabled (mask option) and the LVION and LVIE bits are set. The LVIF flag is reset by clearing the LVIE bit. The LVI circuit is rearmed by again setting the LVIE bit.

LVIE — Low voltage interrupt enable

- 1 (set) — Low voltage interrupt and flag generation is enabled.
- 0 (clear) — Low voltage interrupt and flag generation is disabled.

Setting this bit enables the low voltage flag and interrupt generation. A CPU interrupt request will then be generated whenever the LVIF bit becomes set and the I-bit in the CCR is clear.

LVION — Low voltage interrupt on

- 1 (set) — Power is supplied to the LVI circuitry.
- 0 (clear) — LVI circuitry is disconnected from the power supply.

Setting this bit applies power to the LVI circuitry. If the LVI function is not used this bit should be cleared to save power.

Note: This bit must be set at least one instruction cycle before setting the LVIE bit, to give the LVI circuitry time to stabilize.

SC — System clock option

- 1 (set) – Bus clock f_{OP} equals $f_{OSC1}/4$ (slow mode)
- 0 (clear) – Bus clock f_{OP} equals $f_{OSC1}/2$ (normal operation)

After power on reset the internal bus frequency is $f_{OSC1}/2$. If the SC (system clock) bit is set, the bus frequency is reduced to $f_{OSC1}/4$. However, this does not affect the DTMF generator, which continues to operate at $f_{OSC1}/2$.

IRQ — Interrupt sensitivity

IRQ edge or level sensitivity

- 1 (set) – IRQ input edge and level sensitive
- 0 (clear) – IRQ input edge sensitive

2.4 Pin descriptions**2.4.1 VDD and VSS**

Power is supplied to the microcomputer via these two pins. VDD is the positive supply pin and VSS is the ground pin.

It is in the nature of CMOS designs that very fast signal transitions occur on the MCU pins. These short rise and fall times place very high short-duration current demands on the power supply. To prevent noise problems, special care must be taken to provide good power supply bypassing at the MCU. Bypass capacitors should have good high-frequency characteristics and be as close to the MCU as possible. Bypassing requirements vary, depending on how heavily the MCU pins are loaded.

2.4.2 \overline{IRQ}

This is an input-only pin for external interrupt sources. Interrupt triggering is selected using the IRQ bit in the SOR register, to be one of two options: either edge and level sensitive or edge sensitive only.

The \overline{IRQ} pin contains an internal Schmitt trigger as part of its input to improve noise immunity.

2.4.3 $\overline{\text{RESET}}$

This active low I/O pin is used to reset the MCU. Applying a logic zero to this pin forces the device to a known start-up state. An external RC-circuit can be connected to this pin to generate a power-on reset (POR) if required. In this case, the time constant must be great enough (at least 100ms) to allow the oscillator circuit to stabilise. This input has an internal Schmitt trigger to improve noise immunity. When a low voltage reset condition occurs internally, the $\overline{\text{RESET}}$ pin provides an active-low open drain output signal that may be used to reset external hardware. Other internal reset conditions are not visible at the $\overline{\text{RESET}}$ pin.

2.4.4 PA0–PA7/keyboard interrupt

The eight I/O lines that comprise port A are configured as inputs during reset. Port A shares its pins with the keyboard interrupt function. Each line has an internal pull-up resistor.

2.4.5 PB0–PB7

The eight I/O lines that comprise port B are configured as inputs during reset. Lines PB0 and PB1 have open drain outputs, lines PB2 and PB3 have internal pull-up resistors and lines PB4–PB7 have internal pull-down resistors.

2.4.6 PC0–PC7

During reset, the eight I/O lines of port C are configured as inputs and each has an internal pull-up resistor.

Note: These pins are not available on the 28-pin version.

2.4.7 PD0–PD7

During reset, the eight lines of port D are configured as inputs. As all port D pins are open drain outputs, an external pull-up resistor is needed when a pin is used as an output.

Note: These pins are not available on the 28-pin version.

2.4.8 TCAP1, TCMP1, TCAP2, TCMP2

These four pins are connected to the 16-bit programmable timer system. TCAP1 and TCAP2 are the timer input capture pins. TCMP1 and TCMP2 are the output compare pins for the timer. TCMP1 and TCMP2 are open drain outputs, therefore each pin requires an external pull-up resistor when it is used as an output.

2.4.9 TNO and TNX

The TNO output provides dual tone DTMF or melody under program control. TNO is an open-drain output, and therefore requires an external pull-up resistor. The TNX output provides pacifier tones under program control.

2.4.10 OSC1 and OSC2

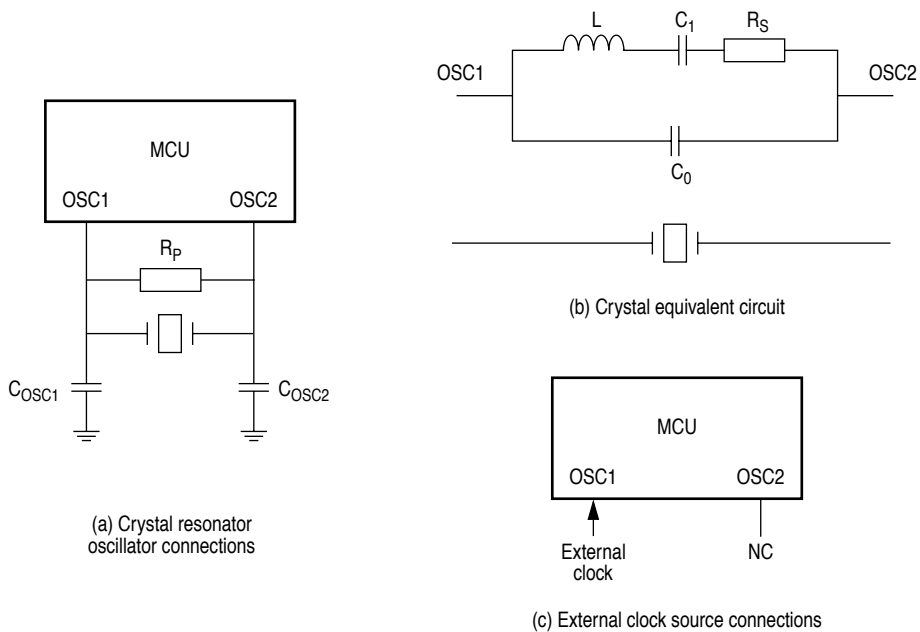
These pins provide control input for an on-chip oscillator circuit. A crystal or external clock signal connected to these pins supplies the oscillator clock. The oscillator frequency of 3.579 MHz provides the time base for the real-time clock and the DTMF/melody generator.

2.4.10.1 Crystal

The circuit shown in [Figure 2-2\(a\)](#) is recommended when using either a crystal or a ceramic resonator. [Figure 2-2\(d\)](#) provides the recommended capacitance and feedback resistance values. The internal oscillator is designed to interface with an AT-cut parallel-resonant quartz crystal resonator in the frequency range specified for f_{OSC} (see [Section 10.4](#)). Use of an external CMOS oscillator is recommended when crystals outside the specified ranges are to be used. The crystal and associated components should be mounted as close as possible to the input pins to minimize output distortion and start-up stabilization time. The manufacturer of the particular crystal being considered should be consulted for specific information.

2.4.10.2 External clock

An external clock should be applied to the OSC1 input, with the OSC2 pin left unconnected, as shown in [Figure 2-2\(c\)](#). The t_{OXOV} specification (see [Section 10.4](#)) does not apply when using an external clock input. The equivalent specification of the external clock source should be used in lieu of t_{OXOV} .



Crystal

	2MHz	4MHz	Unit
$R_S(\text{max})$	400	75	Ω
C_0	5	7	pF
C_1	8	12	fF
C_{OSC1}	15 – 40	15 – 30	pF
C_{OSC2}	15 – 30	15 – 25	pF
R_P	10	10	M Ω
Q	30 000	40 000	—

(d) Crystal resonator parameters

Figure 2-2 Oscillator connections

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3

MEMORY AND REGISTERS

The MC68HC05F4 has a 16K byte memory map consisting of registers (for I/O, control and status), user RAM, user ROM, EEPROM, bootloader ROM and reset and interrupt vectors as shown in [Figure 3-1](#).

3.1 Registers

All the I/O, control and status registers of the MC68HC05F4 are contained within the first 64 byte block of the memory map, as detailed in [Table 3-1](#).

3.2 RAM

The user RAM consists of 256 bytes of memory, from \$0040 to \$013F. This is shared with a 64 byte stack area. The stack begins at \$00FF, and may extend down to \$00C0.

Note: Using the stack area for data storage or temporary work locations requires care to prevent the data from being overwritten due to stacking from an interrupt or subroutine call.

3.3 ROM

The user ROM occupies 3840 bytes of memory, from \$3000 to \$3EFF. In addition, there are 16 bytes of user vectors, from \$3FF0 to \$3FFF.

MC68HC05F4

\$0000	I/O (64 bytes)	\$00 Port A data (PORTA)
		\$01 Port B data (PORTB)
		\$02 Port C data ¹ (PORTC)
		\$03 Port D data ¹ (PORTD)
\$0040	RAM (384 bytes)	\$04 Port A DDR (DDRA)
		\$05 Port B DDR (DDRB)
		\$06 Port C DDR ¹ (DDRC)
		\$07 Port D DDR ¹ (DDRD)
\$00C0	Stack ↑	\$08 Core time control/status (CTCSR)
\$00FF		\$09 Core timer counter (CTCR)
\$0140	Unused	\$0A Unused
\$0200	EEPROM (256 bytes)	\$0B Reserved
		\$0C Reserved
\$02FF	Unused	\$0D DTMF row frequency counter (FCR)
		\$0E DTMF column frequency counter (FCC)
\$3000	User ROM (3840 bytes)	\$0F DTMF tone control (TNCR)
		\$10 Key control (KCR)
		\$11 System options (SOR)
		\$12-\$1B Unused
		\$1C EEPROM Programming (EEPROG)
		\$1D-\$1E Unused
		\$1F Reserved
\$3F00	Bootloader ROM (240 bytes)	\$20 Capture 1 high (ICR1H)
		\$21 Capture 1 low (ICR1L)
		\$22 Compare 1 high (OCR1H)
		\$23 Compare 1 low (OCR1L)
		\$24 Capture 2 high (ICR2H)
		\$25 Capture 2 low (ICR2L)
\$3FF0	User vectors (16 bytes)	\$26 Compare 2 high (OCR2H)
		\$27 Compare 2 low (OCR2L)
\$3FFF		\$28 Timer counter high (CNTH)
		\$29 Timer counter low (CNTL)
		\$2A Alternate counter high (ACNTH)
		\$2B Alternate counter low (ACNTL)
		\$2C Timer control 1 (TCR1)
		\$2D Timer control 2 (TCR2)
		\$2E Timer status (TSR)
		\$2F-\$3F Unused

1. Not available in 28-pin package.

Figure 3-1 MC68HC05F4 memory map

Table 3-1 Register outline

Register Name	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Port A data (PORTA)	\$0000	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0	undefined
Port B data (PORTB)	\$0001	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0	undefined
Port C data (PORTC) ⁽¹⁾	\$0002	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0	undefined
Port D data (PORTD) ⁽¹⁾	\$0003	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0	undefined
Port A data direction (DDRA)	\$0004									0000 0000
Port B data direction (DDRB)	\$0005									0000 0000
Port C data direction (DDRC) ⁽¹⁾	\$0006									0000 0000
Port D data direction (DDRD) ⁽¹⁾	\$0007									0000 0000
Core timer control/status (CTCSR)	\$0008	CTOF	RTIF	CTOFE	RTIE	RTOF	RRTIF	RT1	RT0	uu00 0011
Core timer counter (CTCR)	\$0009									0000 0000
	\$000A–C									
DTMF row freq. control (FCR)	\$000D	0	0	0	FCR4	FCR3	FCR2	FCR1	FCR0	undefined
DTMF column freq. control (FCC)	\$000E	0	0	0	FCC4	FCC3	FCC2	FCC1	FCC0	undefined
DTMF tone control (TNCR)	\$000F	MS1	MS0	TGER	TGEC	TNOE	0	0	0	0000 0000
Key control (KCR)	\$0010	KF	KIE	0	0	0	0	0	0	0000 0000
System options (SOR)	\$0011	LVIF	LVIE	LVION	SC	IRQ	0	0	0	0000 0000
	\$0012–1B									
EEPROM programming (EEPROM)	\$001C	0	CPEN	0	ER1	ER0	LATCH	EERC	EEPGM	0000 0000
	\$001D–1F									
Input capture 1 high (ICR1H)	\$0020	(bit 15)							(bit 8)	undefined
Input capture 1 low (ICR1L)	\$0021									undefined
Output compare 1 high (OCR1H)	\$0022	(bit 15)							(bit 8)	undefined
Output compare 1 low (OCR1L)	\$0023									undefined
Input capture 2 high (ICR2H)	\$0024	(bit 15)							(bit 8)	undefined
Input capture 2 low (ICR2L)	\$0025									undefined
Output compare 2 high (OCR2H)	\$0026	(bit 15)							(bit 8)	undefined
Output compare 2 low (OCR2L)	\$0027									undefined
Timer counter high (CNTH)	\$0028	(bit 15)							(bit 8)	1111 1111
Timer counter low (CNTL)	\$0029									1111 1100
Alternate counter high (ACNTH)	\$002A	(bit 15)							(bit 8)	1111 1111
Alternate counter low (ACNTL)	\$002B									1111 1100
Timer control 1 (TCR1)	\$002C	IC1E	IC1E	OC1E	TOIE	CO1E	IEDG1	IEDG2	OLVL1	0000 0uu0
Timer control 2 (TCR2)	\$002D	0	0	OC1E	0	CO2E	0	0	OLVL2	0000 0000
Timer status (TSR)	\$002E	IC1F	IC2F	OC1F	TOF	TCAP1	TCAP2	OC2F	0	uuuu uu0
	\$002F									

u = undefined

(1) Not available in 28-pin packages

Note: For compatibility, unused bits (shaded) should always be cleared, when writing to them.

3.4 Bootloader ROM

The MC68HC05F4 has 240 bytes of bootloader ROM, from \$3F00 to \$3FEF.

3

3.5 EEPROM

256 bytes of user EEPROM reside at addresses \$0200 to \$02FF.

Programming or erasing the EEPROM can be done by the user on a single byte basis; erasing may also be performed on a block or bulk basis. All programming or erasing is accomplished by manipulating the programming register (EERPROG), located at address \$001C.

Note: The erased state of an EEPROM byte is '\$FF'. This means that a write forces zeros to the bits specified, whilst bits defined as ones are unchanged by a write operation.

Caution: There is a restriction on the use of indexed addressing for EEPROM read operations. When the base address of an indexed read of an EEPROM location is within the EEPROM address range (\$0400 to \$04FF), the read may not be successful. e.g. LDA (BASE ADDRESS), X – may not give the correct result when the base address is in the range \$0400 to \$04FF. However, if the base address is outwith the EEPROM address range, the read operation will be successful. This restriction applies to all operations capable of using indexed addressing.

3.5.1 EEPROM programming register

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
EEPROM programming (EERPROG)	\$001C	0	CPEN	0	ER1	ER0	LATCH	EERC	EEPGM	0000 0000

CPEN — Charge pump enable

- 1 (set) – Charge pump enabled.
- 0 (clear) – Charge pump disabled.

When set, CPEN enables the charge pump which produces the internal programming voltage. This bit should be set at the same time as the LATCH bit. The programming voltage will not be available until EEPGM is set. The charge pump should be disabled when not in use. CPEN is readable and writable and is cleared by reset.

ER1, ER0 — Erase select bits

ER1 and ER0 are used to select either single byte programming or one of three erase modes: byte, block, or bulk. Table 3-2 shows the mode selected for each bit configuration. These bits are readable and writable and are cleared by reset.

Table 3-2 Erase modes

ER1	ER0	Mode
0	0	Program
0	1	Byte erase
1	0	Block erase
1	1	Bulk erase

- In byte erase mode, only the selected byte is erased.
- In block erase mode, a 64-byte block of EEPROM is erased. The EEPROM memory space is divided into four 64-byte blocks (\$0200 – \$023F, \$0240 – \$027F, \$0280 – \$02BF and \$02C0 – \$02FF) and performing a block erase on any address within a block will erase the entire block.
- In bulk erase mode, the entire 256 bytes of EEPROM are erased.

LATCH — EEPROM latch bit

- 1 (set) – EEPROM address and data buses are configured for programming.
- 0 (clear) – EEPROM address and data buses are configured for normal operation.

When set, the LATCH bit configures the EEPROM address and data buses for programming. In addition, writes to the EEPROM array cause the address and data buses to be latched. This bit is readable and writable, but reads from the EEPROM array are inhibited if the LATCH bit is set and a write to the EEPROM space has taken place. When this bit is clear, address and data buses are configured for normal operation. Reset clears this bit.

EERC — EEPROM RC oscillator control

- 1 (set) – Use internal RC oscillator for EEPROM.
- 0 (clear) – Use CPU clock for EEPROM.

When this bit is set, the EEPROM memory array uses the internal RC oscillator instead of the CPU clock. After setting the EERC bit, the user should wait a time t_{RCON} to allow the RC oscillator to stabilize. This bit is readable and writable and should be set by the user when the internal bus frequency falls below 1.5MHz. Reset clears this bit.

EEPGM — EEPROM programming power enable

- 1 (set) – Programming power connected to the EEPROM array.
- 0 (clear) – Programming power switched off.

EEPGM must be set to enable the EEPGM function. When set, EEPGM turns on the charge pump and enables the programming (or erasing) power to the EEPROM array. When clear, this power is switched off. This will enable pulsing of the programming voltage to be controlled internally. This bit can be read at any time, but can only be written to if LATCH = 1, i.e. if LATCH is not set, then EEPGM cannot be set. Reset clears this bit.

3.5.2 Programming and erasing procedures

To program a byte of EEPROM, set LATCH = CPEN = 1, set ER1 = ER0 = 0, write data to the desired address and then set EEPGM for a time t_{EPGM} .

There are three possibilities for erasing data from the EEPROM array, depending on how much data is affected.

- To erase a byte of EEPROM, set LATCH = CPEN = 1, set ER1 = 0 and ER0 = 1, write data to the desired address and then set EEPGM for a time t_{EByte} .
- To erase a block of EEPROM, set LATCH = CPEN = 1, set ER1 = 1 and ER0 = 0, write data to any address in the block and then set EEPGM for a time t_{EBlock} .
- To bulk erase the EEPROM, set LATCH = CPEN = 1, set ER1 = ER0 = 1, write data to any address in the array and then set EEPGM for a time t_{EBulk} .

To terminate the programming or erase sequence, clear EEPGM, wait for a time t_{FPV} to allow the programming voltage to fall, and then clear LATCH and CPEN to release the buses. Following each erase or programming sequence, clear all programming control bits.

3.5.3 Sample EEPROM programming sequence

The following program is an example of the EEPROM programming sequence, using the timer to implement the required delay and assuming a 1 MHz bus frequency.

```

TCSR EQU $0008          TIMER CONTROL AND STATUS REGISTER
TCNT EQU $0009          TIMER COUNTER REGISTER
TOF EQU 7               TOF BIT OF TCSR
PROG EQU $001C          EEPROM PROGRAM REGISTER
CPEN EQU 6              CHARGE PUMP ENABLE BIT
ER1 EQU 4               ERASE SELECT BIT 1
ER0 EQU 3               ERASE SELECT BIT 0
LATCH EQU 2             LATCH BIT
EERC EQU 1              RC/OSC SELECTOR BIT
EEPGM EQU 0             EEPROM PROGRAM BIT
EESTART EQU $0200       START ADDRESS OF EEPROM
SUMPIN EQU $FF          DUMMY DATA

```

```

ORG $0680
START EQU *
    BSET EERC, PROG      SELECT RC OSCILLATOR
    BSR  DELAY           RC OSCILLATOR STABILIZATION
    BSET CPEN, PROG      TURN ON CHARGE PUMP
    BSET LATCH, PROG     ENABLE LATCH BIT
    BCLR ER1, PROG       SELECT PROGRAM (NOT ERASE)
    BCLR ER0, PROG       SELECT PROGRAM (NOT ERASE)

    LDA #SUMPIN          GET DATA
    STA EESTART
    BSET EEPGM, PROG     ENABLE PROGRAMMING POWER
    JSR  DELAY           WAIT FOR PROGRAMMING TIME
    BCLR EEPGM, PROG     CLEAR EEPGM

    JSR  DELAY           WAIT FOR PROG VOLTAGE TO FALL
    BCLR LATCH, PROG     CLEAR LATCH
    BCLR CPEN, PROG      DISABLE CHARGE PUMP
    CMP  EESTART         VERIFY
    BNE  OUT1            CLEAR CARRY BIT IF NO ERROR
    CLC

OUT  RTS

OUT1 SEC                FLAG AN ERROR
     RTS

```

*THIS ROUTINE GIVES A 15MS (+/-1MS) DELAY AT 1 MHZ BUS. THE SAME DELAY
* ROUTINE IS USED IN THIS EXAMPLE FOR SIMPLICITY, USING THE LONGEST DELAY
* TIME. USERS WILL WANT TO WRITE SHORTER DELAY ROUTINES FOR APPLICATIONS
* IN WHICH SPEED IS IMPORTANT.

```

DELAY EQU *
    LDX #15              COUNT OF 15
TIMLP BCLR TOF, TCSR    CLEAR TOF
      BRCLR TOF, TCSR   WAIT FOR TOF FLAG
      DECX
      BNE TIMLP         COUNT DOWN TO 0
      RTS

```

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PARALLEL INPUT/OUTPUT PORTS

The MC68HC05F4 has a total of 32 I/O lines, arranged as four 8-bit ports. The I/O lines are individually programmable as either input or output, under the software control of the data direction registers. Port A can also be configured to respond to keyboard interrupts.

To avoid glitches on the output pins, data should be written to the I/O port data register before writing ones to the corresponding data direction register bits to set the pins in output mode.

4.1 Input/output programming

The bidirectional port lines may be programmed as inputs or outputs under software control. The direction of each pin is determined by the state of the corresponding bit in the port data direction register (DDR). Each I/O port has an associated DDR. Any I/O port pin is configured as an output if its corresponding DDR bit is set to a logic one. A pin is configured as an input if its corresponding DDR bit is cleared.

At power-on or reset, all DDRs are cleared, thus configuring all port pins as inputs. The data direction registers can be written to or read by the MCU. During the programmed output state, a read of the data register actually reads the value of the output data latch and not the I/O pin. The operation of the standard port hardware is shown schematically in [Figure 4-2](#).

This is further summarized in [Table 4-1](#), which shows the effect of reading from, or writing to an I/O pin in various circumstances. Note that the read/write signal shown is internal and not available to the user.

4.2 Port A

Port A is an 8-bit bidirectional port which is equipped with a keyboard interrupt. All eight lines have internal pull-up resistors, which are required when the port is in input mode. On reset, this port is configured as a standard I/O port comprising a data register and a data direction register.

4

Reset does not affect the state of the data register, but clears the data direction register, thereby returning all ports pins to input mode. Writing a 1 to any DDR bit sets the corresponding port pin to output mode. As every pin configured as an input contributes to the keyboard interrupt, it is possible to disable a single pin by configuring it as an output.

4.2.1 Keyboard interrupt

Provided that the interrupt mask bit of the condition code register is cleared, the keyboard interrupt facility is enabled by setting the keyboard interrupt bit (KIE) in the Key Control register.

On detection of a high-to-low transition, the interrupt inputs PA6 and PA7 are triggered. The trigger edges of the interrupt lines, PA0–PA5, can be programmed using the EDG0–EDG5 bits in the Key Control register. If one of these bits is cleared, after reset the corresponding interrupt is falling-edge sensitive. If, however, one of them is set, after reset the corresponding interrupt is rising-edge sensitive. The internal pull-up resistors of input lines, PA7–PA0, are disabled, if rising-edge sensitivity is selected.

When a correct transition is detected, on any of this port's pins, a keyboard interrupt request is generated, and the corresponding interrupt status flag of the interrupt status register, IRSTATE, is set. The interrupt status register is an 8-bit register which has the same address as PORTA, \$0000. This register can be read if the KEYMUX bit in the system option register is set. If KIE is set, a keyboard interrupt is generated and the keyboard status flag, KF, is set by generating the logical OR of the eight interrupt state register outputs.

The 8 interrupt state register flags can be reset in three ways:

- 1) Completely, if the chip is reset.
- 2) Completely, if a 1 is written to KEYCLR, in the system option register.
- 3) Individually, if a 1 is written to the corresponding bit position of the interrupt state register (\$00 with KEYMUX = 1, in the system option register).

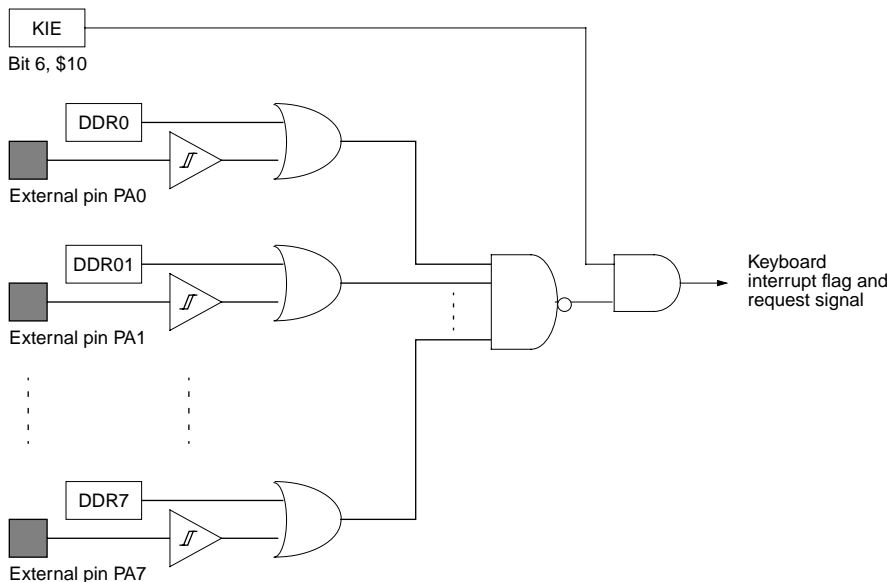


Figure 4-1 Structure of port with keyboard interrupt

4.2.1.1 Key control register

This register contains two bits which are used to control the keyboard interrupt facility. The keyboard interrupt and flag setting is enabled by setting the keyboard interrupt enable bit.

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Key control register (KCR)	\$0010	KF	KIE	0	0	0	0	0	0	0000 0000

KF — Keyboard interrupt status flag

- 1 (set) — A high to low transition has occurred on one of the port pins.
- 0 (clear) — No high to low transition has occurred on any of the port pins.

This bit is set when a high to low transition is detected on any of the port A pins and if KIE equals one. The KF flag is cleared by accessing the port A register.

KIE — keyboard interrupt enable

- 1 (set) – Keyboard interrupt and flag setting enabled.
- 0 (clear) – Keyboard interrupt and flag setting disabled.

An interrupt can only be generated if KIE and KF are both set and the I-bit in the CCR is clear.

4

4.3 Port B

Port B is an 8-bit bidirectional port which does not share any of its pins with other subsystems. The lines PB0 and PB1 have open drain outputs, PB2 and PB3 have internal pull-up resistors and lines PB4–PB7 have internal pull-down resistors.

Reset does not affect the state of the data register, but clears the data direction register, thereby returning all port pins to input mode. Writing a '1' to any DDR bit sets the corresponding port pin to output mode.

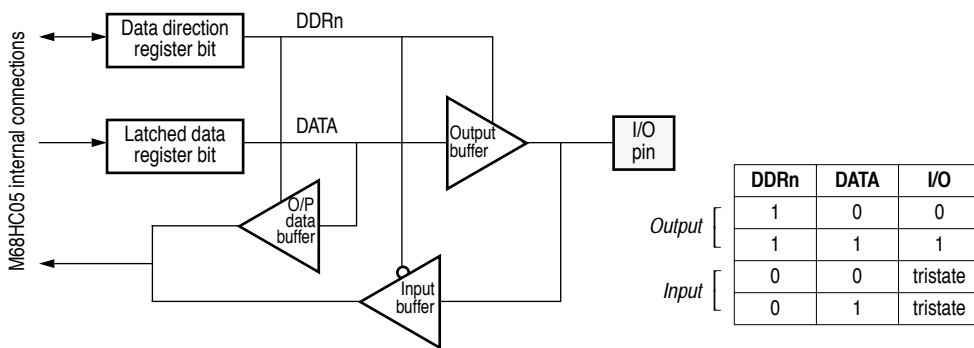


Figure 4-2 Standard I/O port structure

Table 4-1 I/O pin states

R/W	DDRn	Action of MCU write to/read of data bit
0	0	The I/O pin is in input mode. Data is written into the output data latch.
0	1	Data is written into the output data latch, and output to the I/O pin.
1	0	The state of the I/O pin is read.
1	1	The I/O pin is in output mode. The output data latch is read.

4.4 Port C

Port C is an 8-bit bidirectional port which does not share any of its pins with other subsystems. All eight lines have internal pull-up resistors. Port C is not available on the 28-pin package.

Reset does not affect the state of the data register, but clears the data direction register, thereby returning all port pins to input mode. Writing a '1' to any DDR bit sets the corresponding port pin to output mode. The port C lines have internal pull-up resistors.

4.5 Port D

Port D is an 8-bit bidirectional port which does not share any of its pins with other subsystems. It has open drain outputs, which means when a pin is being used as an output, an external pull-up resistor is required. Port D is not available on the 28-pin package.

Note: As the voltage at port D is driven above V_{DD} , the protection device will begin to conduct and tend to clamp the input voltage to protect the input buffer. The voltage at which this occurs varies significantly from lot to lot and over the operating temperature range. At room temperature, the pin typically does not draw any current until approximately 18V.

4.6 Port registers

The following sections explain in detail the individual bits in the data and control registers associated with the ports.

4

4.6.1 Port data registers (Ports A, B, C and D)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Port A data (PORTA)	\$0000	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0	undefined
Port B data (PORTB)	\$0001	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0	undefined
Port C data (PORTC)	\$0002	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0	undefined
Port D data (PORTD)	\$0003	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0	undefined

Each bit of port A – port D can be configured as input or output via the corresponding data direction bit in the port data direction register (DDRx).

Reset does not affect the state of the port A – port D data registers.

4.6.2 Data direction registers (DDRA, DDRB, DDRC and DDRD)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Port A data direction (DDRA)	\$0004									0000 0000
Port B data direction (DDR B)	\$0005									0000 0000
Port C data direction (DDRC)	\$0006									0000 0000
Port D data direction (DDRD)	\$0007									0000 0000

Writing a '1' to any bit configures the corresponding port pin as an output; conversely, writing any bit to '0' configures the corresponding port pin as an input.

Reset clears these registers, thus configuring all port pins as inputs.

5

CORE TIMER

The MC68HC05F4 has a 15-stage ripple counter called the core timer (CTIMER). Features of this timer are: timer overflow, power-on reset (POR), real time interrupt (RTI) with four selectable interrupt rates and a computer operating properly (COP) watchdog timer.

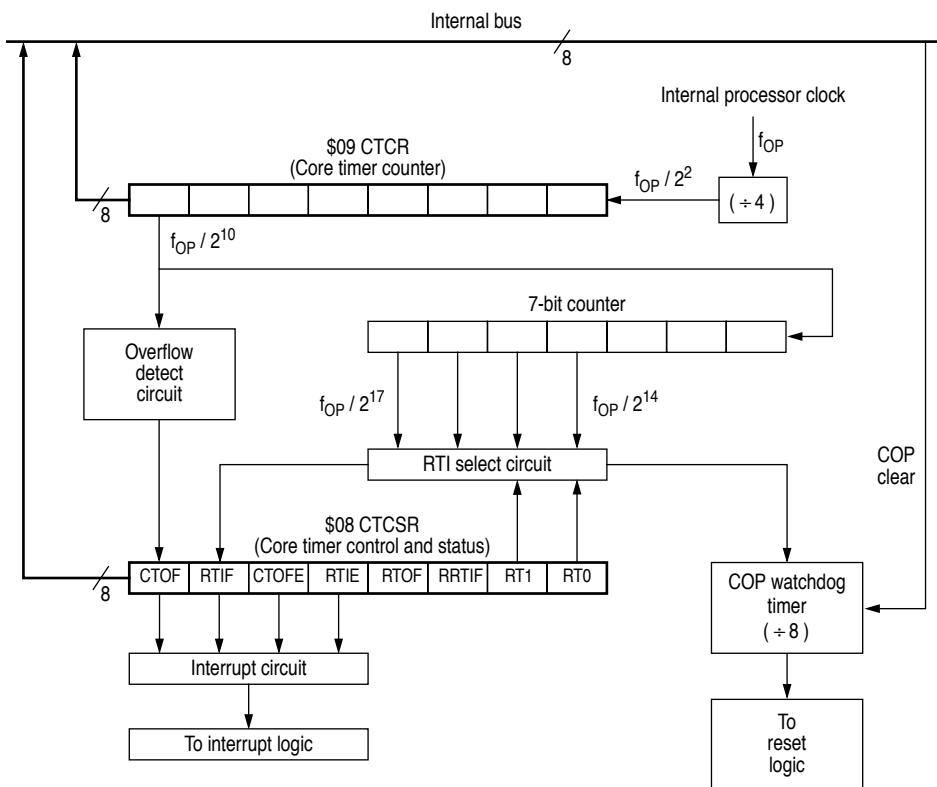


Figure 5-1 Core timer block diagram

As shown in [Figure 5-1](#), the timer is driven by the internal bus clock divided by four with a fixed prescaler. This signal drives an 8-bit ripple counter. The value of this 8-bit ripple counter can be read by the CPU at any time, by accessing the CTIMER counter register (CTCR) at address \$09. A timer overflow function is implemented on the last stage of this counter, giving a possible interrupt at the rate of $f_{OP}/1024$. (The POR signal (t_{PORL}) is also derived from this register, at $f_{OP}/4064$.) The counter register circuit is followed by four more stages, with the resulting clock ($f_{OP}/16384$) driving the real time interrupt circuit. The RTI circuit consists of three divider stages with a 1-of-4 selector. The output of the RTI circuit is further divided by 8 to drive the COP watchdog timer circuit. The RTI rate selector bits, and the RTI and CTIMER overflow enable bits and flags, are located in the CTIMER control and status register (CTCSR) at location \$08.

CTOF (core timer overflow flag) is a clearable, read-only status bit and is set when the 8-bit ripple counter rolls over from \$FF to \$00. A CPU interrupt request will be generated if CTOFE is set. Clearing the CTOF is done by writing a '0' to it. Writing a '1' to CTOF has no effect on the bit's value. Reset clears CTOF.

When CTOFE (core timer overflow enable) is set, a CPU interrupt request is generated when the CTOF bit is set. Reset clears CTOFE.

The core timer counter register (CTCR) is a read-only register that contains the current value of the 8-bit ripple counter at the beginning of the timer chain. This counter is clocked at $f_{OP}/4$ and can be used for various functions including a software input capture. Extended time periods can be attained using the CTIMER overflow function to increment a temporary RAM storage location thereby simulating a 16-bit (or more) counter.

The power-on cycle clears the entire counter chain and begins clocking the counter. After t_{PORL} cycles, the power-on reset circuit is released, which again clears the counter chain and allows the device to come out of reset. At this point, if $\overline{\text{RESET}}$ is not asserted, the timer will start counting up from zero and normal device operation will begin. When $\overline{\text{RESET}}$ is asserted at any time during operation (other than POR), the counter chain will be cleared.

5.1 Real time interrupts (RTI)

The real time interrupt circuit consists of a three stage divider and a 1-of-4 selector. The clock frequency that drives the RTI circuit is $f_{OP}/2^{14}$ (or $f_{OP}/16384$), with three additional divider stages, giving a maximum interrupt period of 4 seconds at a bus frequency (f_{OP}) of 32kHz. Register details are given in [Section 5.2](#).

5.2 Core timer registers

5.2.1 Core timer control and status register (CTCSR)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Core timer control/status (CTCSR)	\$0008	CTOF	RTIF	CTOFE	RTIE	RTOF	RRTIF	RT1	RT0	uu00 0011

CTOF — Core timer overflow

- 1 (set) – Core timer overflow has occurred.
- 0 (clear) – No core timer overflow interrupt has been generated.

CTOF is a read-only status bit and is set when the core timer counter register rolls over from \$FF to \$00; an interrupt request will be generated if CTOFE is set. When set, CTOF may be cleared by writing a '1' to RTOF.

RTIF — Real time interrupt flag

- 1 (set) – A real time interrupt has occurred.
- 0 (clear) – No real time interrupt has been generated.

RTIF is a read-only status bit and is set when the output of the chosen stage becomes active; an interrupt request will be generated if RTIE is set. When set, the bit may be cleared by writing a '1' to RRTIF. Reset also clears this bit.

CTOFE — Core timer overflow enable

- 1 (set) – Core timer overflow interrupt is enabled.
- 0 (clear) – Core timer overflow interrupt is disabled.

Setting this bit enables the core timer overflow Interrupt. A CPU interrupt request will then be generated whenever the CTOF bit becomes set and the I-bit in the CCR is clear. Clearing this bit disables the core timer overflow interrupt capability.

RTIE — Real time interrupt enable

- 1 (set) – Real time interrupt is enabled.
- 0 (clear) – Real time interrupt is disabled.

Setting this bit enables the real time interrupt. A CPU interrupt request will then be generated whenever the RTIF bit becomes set and the I-bit in the CCR is clear. Clearing this bit disables the real time interrupt capability.

RTOF — Reset timer overflow flag

Writing a '1' to this bit clears the timer overflow flag, CTOF. See CTOF description.

RRTIF — Reset real time overflow flag

Writing a '1' to this bit clears the real time interrupt flag, RTIF. See RTIF description.

RT1, RT0 — Real time interrupt rate select

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These two bits select one of four taps from the real time interrupt circuitry. Reset sets both RT0 and RT1 to one, selecting the lowest periodic rate and therefore the maximum time in which to alter them if necessary. The COP reset times are also determined by these two bits. Care should be taken when altering RT0 and RT1 if a timeout is imminent, or the timeout period is uncertain. If the selected tap is modified during a cycle in which the counter is switching, an RTIF could be missed or an additional one could be generated. To avoid problems, the COP should be cleared before changing the RTI taps. See [Table 5-1](#) for some example RTI periods.

Table 5-1 Example RTI periods

			RTI Rates at f_{OP} Frequency Specified			
RT1	RT0	Division ratio	16.384 kHz	447 kHz	895 kHz	1.789 MHz
0	0	2^{14}	1 s	36.7 ms	18.35 ms	9.17 ms
0	1	2^{15}	2 s	73.4 ms	36.7 ms	18.35 ms
1	0	2^{16}	4 s	146.8 ms	73.4 ms	36.7 ms
1	1	2^{17}	8 s	293.6 ms	146.8 ms	73.4 ms

5.2.2 Core timer counter register (CTCR)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Core timer counter (CTCR)	\$0009									0000 0000

The core timer counter register is a read-only register, which contains the current value of the 8-bit ripple counter at the beginning of the timer chain. Reset clears this register.

5.3 Computer operating properly (COP) watchdog timer

The COP watchdog timer function is implemented by taking the output of the RTI circuit and further dividing it by eight, as shown in [Figure 5-1](#). Note that the minimum COP timeout period is seven times the RTI period. This is because the COP will be cleared asynchronously with respect to the value in the core timer counter register/RTI divider, hence the actual COP timeout period will vary between 7x and 8x the RTI period. The minimum COP reset rates are shown in [Table 5-2](#).

The COP function is a mask option, enabled or disabled during device manufacture.

If the COP circuit times out, an internal reset is generated and the normal reset vector is fetched. A COP timeout is prevented by writing a '0' to bit 0 of address \$3FF0. When the COP is cleared, only the final divide-by-eight stage is cleared (see [Figure 5-1](#)).

Table 5-2 Minimum COP reset times

		Minimum COP reset at f_{op} frequency specified				
RT1	RT0	16.384 kHz	447 kHz	895 kHz	1.789 MHz	f_{op}
0	0	7 s	256.9 ms	128.45 ms	64.19 ms	7 x RTI rate
0	1	14 s	513.8 ms	256.9 ms	128.45 ms	7 x RTI rate
1	0	28 s	1.03 s	513.8 s	256.9 ms	7 x RTI rate
1	1	56 s	2.06 s	1.03 s	513.8 ms	7 x RTI rate

5.4 Core timer during WAIT

The CPU clock halts during the WAIT mode, but the timer remains active. If the CTIMER interrupts are enabled, then a CTIMER interrupt will cause the processor to exit the WAIT mode.

5.5 Core timer during STOP

The timer is cleared when going into STOP mode. When STOP is exited by an external interrupt or an external reset, the internal oscillator will restart, followed by an internal processor stabilization delay (t_{PORL}). The timer is then cleared and operation resumes.

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6

16-BIT PROGRAMMABLE TIMER

The timer consists of a 16-bit read-only free-running counter, with a fixed divide-by-four prescaler, plus the input capture/output compare circuitry. The timer can be used for many purposes including measuring pulse length of two input signals and generating two output signals. Pulse lengths for both input and output signals can vary from several microseconds to many seconds. The timer is also capable of generating periodic interrupts or indicating passage of an arbitrary multiple of four CPU cycles. A block diagram is shown in [Figure 6-1](#), and timing diagrams are shown in [Figure 6-2](#), [Figure 6-3](#), [Figure 6-4](#) and [Figure 6-5](#).

The timer has a 16-bit architecture, hence each specific functional segment is represented by two 8-bit registers. These registers contain the high and low byte of that functional segment. Accessing the low byte of a specific timer function allows full control of that function; however, an access of the high byte inhibits that specific timer function until the low byte is also accessed.

The 16-bit programmable timer is monitored and controlled by a group of fifteen registers, full details of which are contained in this section.

Note: A problem may arise if an interrupt occurs in the time between the high and low bytes being accessed. To prevent this, the I-bit in the condition code register (CCR) should be set while manipulating both the high and low byte register of a specific timer function, ensuring that an interrupt does not occur.

6.1 Counter

The key element in the programmable timer is a 16-bit, free-running counter or counter register, preceded by a prescaler that divides the internal processor clock by four. The prescaler gives the timer a resolution of 2 μ s if the internal bus clock is 2 MHz. The counter is incremented during the low portion of the internal bus clock. Software can read the counter at any time without affecting its value.

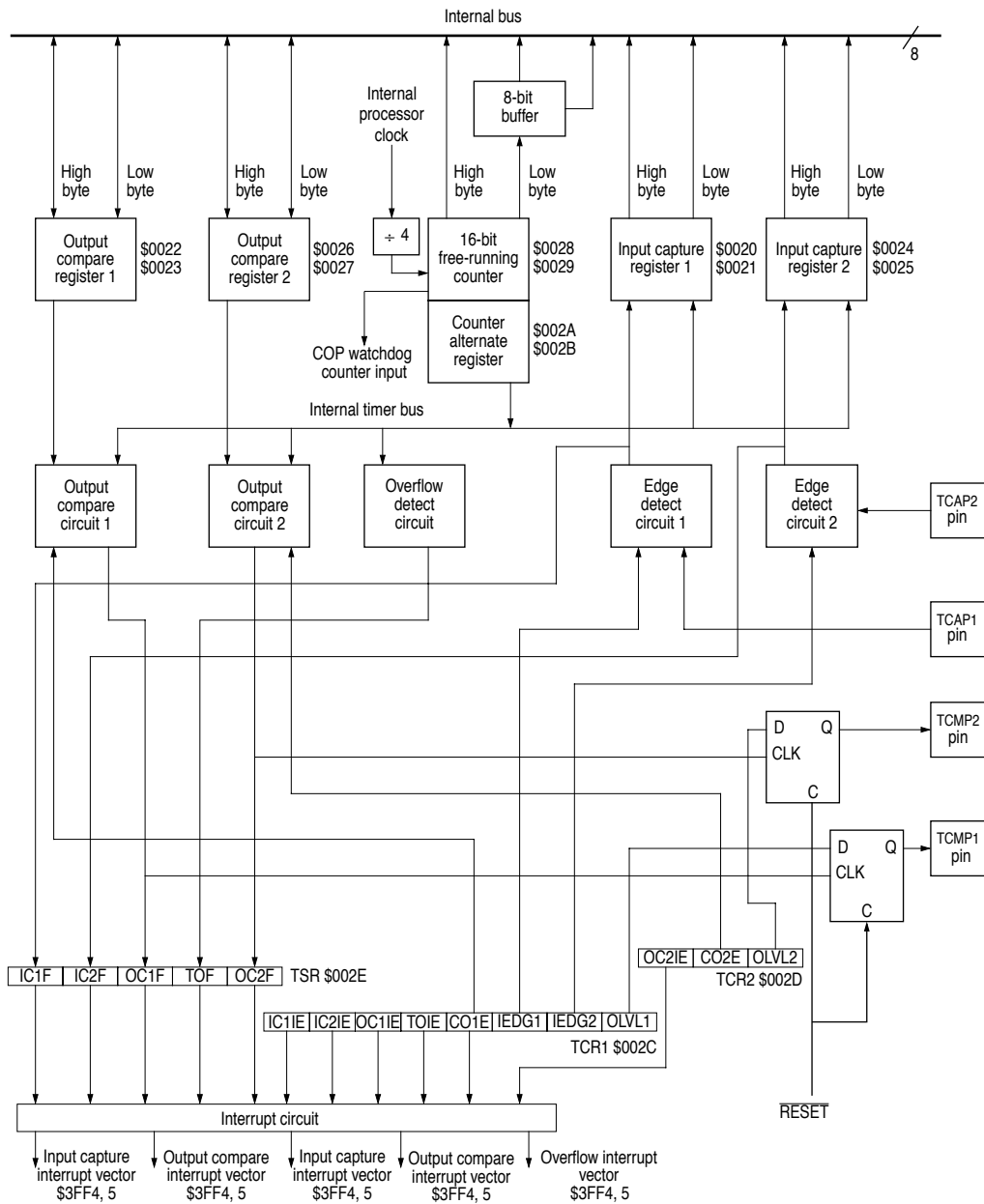


Figure 6-1 16-bit programmable timer block diagram

6.1.1 Counter register and alternate counter register

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Timer counter high (CNTH)	\$0028									1111 1111
Timer counter low (CNTL)	\$0029									1111 1100

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Alternate counter high (ACNTH)	\$002A									1111 1111
Alternate counter low (ACNTL)	\$002B									1111 1100

The double-byte, free-running counter can be read from either of two locations, \$0028 – \$0029 (counter register) or \$002A – \$002B (counter alternate register). A read from only the less significant byte (LSB) of the free-running counter (\$0029 or \$002B) receives the count value at the time of the read. If a read of the free-running counter or alternate counter register first addresses the more significant byte (MSB) (\$0028 or \$002A), the LSB is transferred to a buffer. This buffer value remains fixed after the first MSB read, even if the user reads the MSB several times. This buffer is accessed when reading the free-running counter or alternate counter register LSB and thus completes a read sequence of the total counter value. In reading either the free-running counter or alternate counter register, if the MSB is read, the LSB must also be read to complete the sequence. If the timer overflow flag (TOF) is set when the counter register LSB is read then a read of the timer status register (TSR) will clear the flag.

The counter alternate register differs from the counter register only in that a read of the LSB does not clear TOF. Therefore, where it is critical to avoid the possibility of missing timer overflow interrupts due to clearing of TOF, the alternate counter register should be used.

The free-running counter is set to \$FFFC during power-on and external reset and is always a read-only register. During a power-on reset, the counter begins running after the oscillator start-up delay. Because the free-running counter is 16 bits preceded by a fixed divide-by-4 prescaler, the value in the free-running counter repeats every 262,144 internal bus clock cycles. TOF is set when the counter overflows (from \$FFFF to \$0000); this will cause an interrupt if TOIE is set.

The divide-by-4 prescaler is also reset and the counter resumes normal counting operation. All of the flags and enable bits remain unaltered by this operation. If access has previously been made to the high byte of the free-running counter (\$0028 or \$002A), then the reset counter operation terminates the access sequence.

6.2 Timer control and status

The various functions of the timer are monitored and controlled using the timer control and status registers described below.

6.2.1 Timer control registers 1 and 2 (TCR1 and TCR2)

The two timer control registers TCR1 and TCR2 (\$002C and \$002D) are used to enable the input captures (IC1IE and IC2IE), output compares (OC1IE and OC2E), and timer overflow (TOIE) functions as well as enabling the compare outputs (CO1E and CO2E), selecting input edge sensitivity (IEDG1 and IEDG2) and levels of output polarity (OLVL1 and OLVL2).

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Timer control 1 (TCR1)	\$002C	IC1IE	IC2IE	OC1IE	TOIE	CO1E	IEDG1	IEDG2	OLVL1	0000 0uu0
Timer control 2 (TCR2)	\$002D	0	0	OC2IE	0	CO2E	0	0	OLVL2	0000 0000

IC1IE — Input capture 1 interrupt enable

If this bit is set, a timer interrupt is enabled whenever the IC1F status flag (in the timer status register) is set.

- 1 (set) – Interrupt enabled.
- 0 (clear) – Interrupt disabled.

IC2IE — Input capture 2 interrupt enable

If this bit is set, a timer interrupt is enabled whenever the IC2F status flag (in the timer status register) is set.

- 1 (set) – Interrupt enabled.
- 0 (clear) – Interrupt disabled.

OC1IE — Output compare 1 interrupt enable

If this bit is set, a timer interrupt is enabled whenever the OC1F status flag (in the timer status register) is set.

- 1 (set) – Interrupt enabled.
- 0 (clear) – Interrupt disabled.

TOIE — Timer overflow interrupt enable

If this bit is set, a timer interrupt is enabled whenever the TOF status flag (in the timer status register) is set.

- 1 (set) – Interrupt enabled.
- 0 (clear) – Interrupt disabled.

CO1E — Timer compare 1 output enable

If this bit is set, the output from timer output compare 1 is enabled.

- 1 (set) – Output compare 1 enabled.
- 0 (clear) – Output compare 1 disabled.

IEDG1 — Input edge 1

When IEDG1 is set, a positive-going edge on the TCAP1 pin will trigger a transfer of the free-running counter value to the input capture register 1. When clear, a negative-going edge triggers the transfer.

- 1 (set) – TCAP1 is positive-going edge sensitive.
- 0 (clear) – TCAP1 is negative-going edge sensitive.

IEDG2 — Input edge 2

When IEDG2 is set, a positive-going edge on the TCAP2 pin will trigger a transfer of the free-running counter value to the input capture register 2. When clear, a negative-going edge triggers the transfer.

- 1 (set) – TCAP2 is positive-going edge sensitive.
- 0 (clear) – TCAP2 is negative-going edge sensitive.

OLVL1 — Output level 1

When OLV1 is set a high output level will be clocked into the output level register by the next successful output compare, and will appear on the TCMP1 pin. When clear, it will be a low level which will appear on the TCMP1 pin.

- 1 (set) – A high output level will appear on the TCMP1 pin.
- 0 (clear) – A low output level will appear on the TCMP1 pin.

OC2IE — Output compare 2 interrupt enable

If this bit is set, a timer interrupt is enabled whenever the OC2F status flag (in the timer status register) is set.

- 1 (set) – Interrupt enabled.
- 0 (clear) – Interrupt disabled.

CO2E — Timer compare 2 output enable

If this bit is set, the output from timer output compare 2 is enabled.

- 1 (set) – Output compare 2 enabled.
- 0 (clear) – Output compare 2 disabled.

OLVL2 — Output level 2

When OLV2 is set a high output level will be clocked into the output level register by the next successful output compare, and will appear on the TCMP2 pin. When clear, it will be a low level which will appear on the TCMP2 pin.

- 1 (set) – A high output level will appear on the TCMP2 pin.
- 0 (clear) – A low output level will appear on the TCMP2 pin.

6.2.2 Timer status register (TSR)

The timer status register (\$002E) contains the status bits corresponding to the timer interrupt conditions – IC1F, IC2F, OC1F, TOF, TCAP1, TCAP2 and OC2F.

Accessing the timer status register satisfies the first condition required to clear the status bits. The remaining step is to access the register corresponding to the status bit.

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Timer status (TSR)	\$002E	IC1F	IC2F	OC1F	TOF	TCAP1	TCAP2	OC2F	0	uuuu uu0

IC1F — Input capture 1 flag

This bit is set when the selected polarity of edge is detected by the input capture edge detector 1 at TCAP1; an input capture interrupt will be generated, if IC1IE is set. IC1F is cleared by reading the TSR and then the input capture 1 low register (\$0021).

- 1 (set) – A valid input capture has occurred.
- 0 (clear) – No input capture has occurred.

IC2F — Input capture 2 flag

This bit is set when the selected polarity of edge is detected by the input capture edge detector 2 at TCAP2; an input capture interrupt will be generated if IC2IE is set. IC2F is cleared by reading the TSR and then the input capture 2 low register (\$0025).

- 1 (set) – A valid input capture has occurred.
- 0 (clear) – No input capture has occurred.

OC1F — Output compare 1 flag

This bit is set when the output compare register 1 contents match those of the free-running counter; an output compare interrupt will be generated if OC1IE is set. OC1F is cleared by reading the TSR and then the output compare 1 low register (\$0023).

- 1 (set) – A valid output compare has occurred.
- 0 (clear) – No output compare has occurred.

TOF — Timer overflow status flag

This bit is set when the free-running counter overflows from \$FFFF to \$0000; a timer overflow interrupt will occur if TOIE is set. TOF is cleared by reading the TSR and the counter low register (\$0029).

- 1 (set) – Timer overflow has occurred.
- 0 (clear) – No timer overflow has occurred.

When using the timer overflow function and reading the free-running counter at random times to measure an elapsed time, a problem may occur whereby the timer overflow flag is unintentionally cleared if:

- 1 The timer status register is read or written when TOF is set, and
- 2 The LSB of the free-running counter is read, but not for the purpose of servicing the flag.

Reading the alternate counter register instead of the counter register will avoid this potential problem.

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TCAP1 — Timer capture 1 flag

This bit reflects the current state of the timer capture 1 input.

TCAP2 — Timer capture 2 flag

This bit reflects the current state of the timer capture 2 input.

OC2F — Output compare 2 flag

This bit is set when the output compare register 2 contents match those of the free-running counter; an output compare interrupt will be generated if OC2IE is set. OC2F is cleared by reading the TSR and then the output compare 2 low register (\$0027).

- 1 (set) – A valid output compare has occurred.
- 0 (clear) – No output compare has occurred.

6.3 Input capture

'Input capture' is a technique whereby an external signal is used to trigger a read of the free running counter. In this way it is possible to relate the timing of an external signal to the internal counter value, and hence to elapsed time.

There are two input capture registers: input capture register 1 (ICR1) and input capture register 2 (ICR2).

There are two input capture interrupt enable bits (IC1IE and IC2IE).

6.3.1 Input capture register 1 (ICR1)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Input capture 1 high (ICR1H)	\$0020									Undefined
Input capture 1 low (ICR1L)	\$0021									Undefined

The two 8-bit registers that make up the 16-bit input capture register 1 are read-only, and are used to latch the value of the free-running counter after the input capture edge detector circuit 1 senses a valid transition at TCAP1. The level transition that triggers the counter transfer is defined by the input edge bit (IEDG1). When an input capture 1 occurs, the corresponding flag IC1F in TSR is set. An interrupt can also accompany an input capture 1 provided the IC1IE bit in TCR1 is set. The 8 most significant bits are stored in the input capture register 1 high at \$0020, the 8 least significant bits in the input capture register 1 low at \$0021.

The result obtained from an input capture will be one greater than the value of the free-running counter on the rising edge of the internal bus clock preceding the external transition. This delay is required for internal synchronization. Resolution is one count of the free-running counter, which is four internal bus clock cycles. The free-running counter contents are transferred to the input capture register 1 on each valid signal transition whether the input capture 1 flag (IC1F) is set or clear. The input capture register 1 always contains the free-running counter value that corresponds to the most recent input capture 1. After a read of the input capture register 1 MSB (\$0020), the counter transfer is inhibited until the LSB (\$0021) is also read. This characteristic causes the time used in the input capture software routine and its interaction with the main program to determine the minimum pulse period. A read of the input capture register 1 LSB (\$0021) does not inhibit the free-running counter transfer since the two actions occur on opposite edges of the internal bus clock.

Reset does not affect the contents of the input capture register 1, except when exiting STOP mode (see [Section 6.5](#)).

6.3.2 Input capture register 2 (ICR2)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Input capture 2 high (ICR2H)	\$0024									Undefined
Input capture 2 low (ICR2L)	\$0025									Undefined

The two 8-bit registers that make up the 16-bit input capture register 2 are read-only, and are used to latch the value of the free-running counter after the input capture edge detector circuit 2 senses a valid transition at pin TCAP2. When an input capture 2 occurs, the corresponding flag IC2F in TSR is set. An interrupt can also accompany an input capture 2 provided the IC2IE bit in TCR1 is set. The 8 most significant bits are stored in the input capture 2 high register at \$0024, the 8 least significant bits in the input capture 2 low register at \$0025.

The result obtained from an input capture will be one greater than the value of the free-running counter on the rising edge of the internal bus clock preceding the external transition. This delay is required for internal synchronization. Resolution is one count of the free-running counter, which is four internal bus clock cycles. The free-running counter contents are transferred to the input capture register 2 on each valid signal transition whether the input capture 2 flag (IC2F) is set or clear. The input capture register 2 always contains the free-running counter value that corresponds to the most recent input capture 2. After a read of the input capture register 2 MSB (\$0024), the counter transfer is inhibited until the LSB (\$0025) is also read. This characteristic causes the time used in the input capture software routine and its interaction with the main program to determine the minimum pulse period. A read of the input capture register 2 LSB (\$0024) does not inhibit the free-running counter transfer since the two actions occur on opposite edges of the internal bus clock.

Reset does not affect the contents of the input capture register 2, except when exiting STOP mode (see [Section 6.5](#)).

6.4 Output compare

'Output compare' is a technique which may be used, for example, to generate an output waveform, or to signal when a specific time period has elapsed, by presetting the output compare register to the appropriate value.

There are two output compare registers: output compare register 1 (OCR1) and output compare register 2 (OCR2).

There are two output compare interrupt enable bits (OC1IE and OC2IE).

6.4.1 Output compare register 1 (OCR1)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Output compare 1 high (OCR1H)	\$0022									Undefined
Output compare 1 low (OCR1L)	\$0023									Undefined

The 16-bit output compare register 1 is made up of two 8-bit registers at locations \$0022 (MSB) and \$0023 (LSB). The contents of the output compare register 1 are compared with the contents of the free-running counter continually and, if a match is found, the corresponding output compare flag (OC1F) in the timer status register is set. If the timer compare output enable bit (CO1E) is set, the output level (OLVL1) is transferred to pin TCMP1. The output compare register 1 values and the output level bit should be changed after each successful comparison to establish a new elapsed timeout. An interrupt can also accompany a successful output compare provided the corresponding interrupt enable bit (OC1IE) is set. (The free-running counter is updated every four internal bus clock cycles.)

After a processor write cycle to the output compare register 1 containing the MSB (\$0022), the output compare function is inhibited until the LSB (\$0023) is also written. The user must write both bytes (locations) if the MSB is written first. A write made only to the LSB (\$0023) will not inhibit the compare 1 function. The processor can write to either byte of the output compare register 1 without affecting the other byte. If the timer compare output enable bit (CO1E) is set, the output level (OLVL1) bit is clocked to the output level register and hence to the TCMP1 pin whether the output compare flag 1 (OC1F) is set or clear. The minimum time required to update the output compare register 1 is a function of the program rather than the internal hardware. Because the output compare flag 1 and the output compare register 1 are not defined at power on, and not affected by reset, care must be taken when initializing output compare functions with software. The following procedure is recommended:

- Write to output compare 1 high to inhibit further compares;
- Read the timer status register to clear OC1F (if set);
- Write to output compare 1 low to enable the output compare 1 function.

The purpose of this procedure is to prevent the OC1F bit from being set between the time it is read and the write to the corresponding output compare register.

All bits of the output compare register are readable and writable and are not altered by the timer hardware or reset. If the compare function is not needed, the two bytes of the output compare register can be used as storage locations.

6.4.2 Output compare register 2 (OCR2)

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	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Output compare 2 high (OCR2H)	\$0026									Undefined
Output compare 2 low (OCR2L)	\$0027									Undefined

The 16-bit output compare register 2 is made up of two 8-bit registers at locations \$0026 (MSB) and \$0027 (LSB). The contents of the output compare register 2 are compared with the contents of the free-running counter continually and, if a match is found, the corresponding output compare flag (OC2F) in the timer status register is set. If the timer compare 2 output enable bit (CO2E) is set, the output level (OLVL2) is transferred to pin TCMP2. The output compare register 2 values and the output level bit should be changed after each successful comparison to establish a new elapsed timeout. An interrupt can also accompany a successful output compare provided the corresponding interrupt enable bit (OC2IE) is set. (The free-running counter is updated every four internal bus clock cycles.)

After a processor write cycle to the output compare register 2 containing the MSB (\$0026), the output compare function is inhibited until the LSB (\$0027) is also written. The user must write both bytes (locations) if the MSB is written first. A write made only to the LSB (\$0027) will not inhibit the compare 2 function. The processor can write to either byte of the output compare register 2 without affecting the other byte. If the timer compare output enable bit (CO2E) is set, the output level (OLVL2) bit is clocked to the output level register and hence to the TCMP2 pin whether the output compare 2 flag (OC2F) is set or clear. The minimum time required to update the output compare register 2 is a function of the program rather than the internal hardware. Because the output compare 2 flag and the output compare register 2 are not defined at power on, and not affected by reset, care must be taken when initializing output compare functions with software. The following procedure is recommended:

- Write to output compare 2 high to inhibit further compares;
- Read the timer status register to clear OC2F (if set);
- Write to output compare 2 low to enable the output compare 2 function.

The purpose of this procedure is to prevent the OC2F bit from being set between the time it is read and the write to the corresponding output compare register.

All bits of the output compare register are readable and writable and are not altered by the timer hardware or reset. If the compare function is not needed, the two bytes of the output compare register can be used as storage locations.

6.5 Timer during STOP mode

When the MCU enters STOP mode, the timer counter stops counting and remains at that particular count value until STOP mode is exited by an interrupt. If STOP mode is exited by power-on or external reset, the counter is forced to \$FFFC but if it is exited by an interrupt then the counter resumes from its stopped value.

Another feature of the programmable timer is that if at least one valid input capture edge occurs at one of the TCAP pins while in STOP mode, the corresponding input capture detect circuitry is armed. This action does not wake the MCU or set any timer flags, but when the MCU does wake-up there will be an active input capture flag (and data) from that first valid edge which occurred during STOP mode.

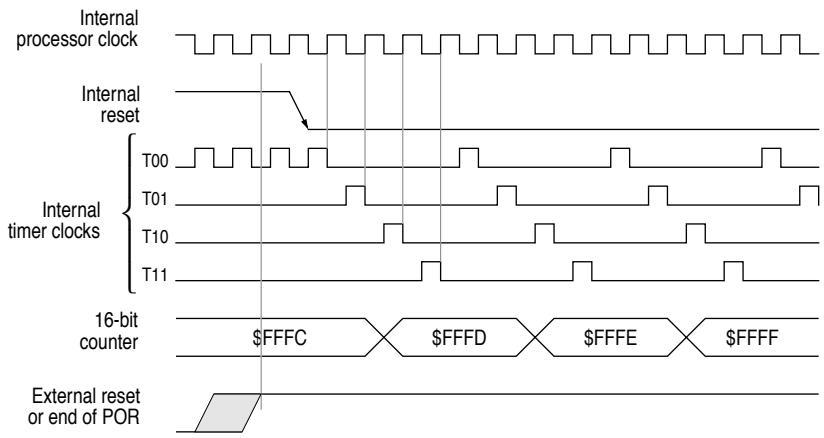
If STOP mode is exited by an external reset then no such input capture flag or data action takes place even if there was a valid input capture edge (at one of the TCAP pins) during STOP mode.

6.6 Timer during WAIT mode

The CPU clock halts during WAIT mode, but the timer keeps running. If a reset is used to exit WAIT mode the counters are forced to \$FFFC. If interrupts are enabled, a timer interrupt will cause the processor to exit WAIT mode.

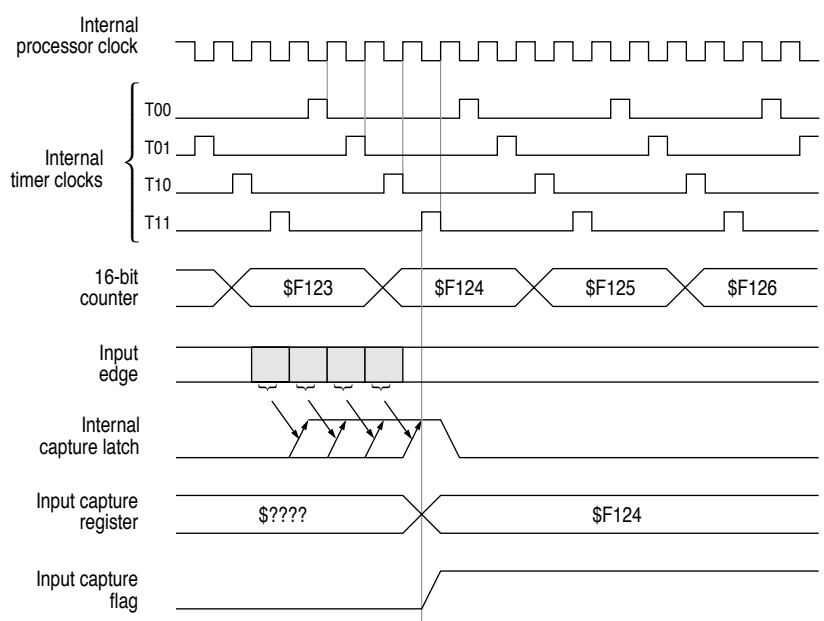
6.7 Timer state diagrams

The relationships between the internal clock signals, the counter contents and the status of the flag bits are shown in [Figure 6-2](#) to [Figure 6-5](#). It should be noted that the signals labelled 'internal' (processor clock, timer clocks and reset) are not available to the user.



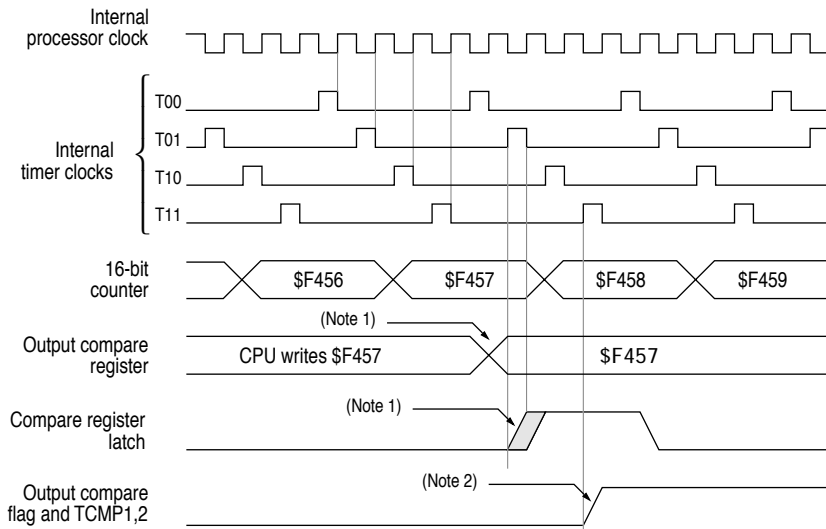
Note: The counter and timer control registers are the only ones affected by power-on or external reset.

Figure 6-2 Timer state timing diagram for reset



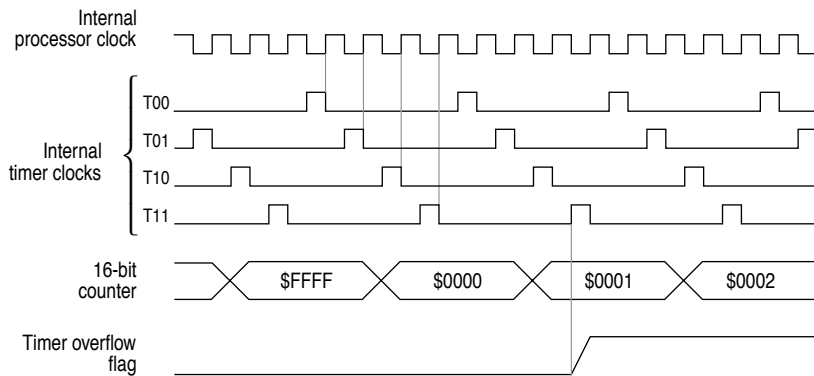
Note: If the input edge occurs in the shaded area from one timer state T10 to the next timer state T10, then the input capture flag will be set during the next T11 state.

Figure 6-3 Timer state timing diagram for input capture



- Note:
- 1 The CPU write to the compare registers may take place at any time, but a compare only occurs at timer state T01. Thus a four cycle difference may exist between the write to the compare register and the actual compare.
 - 2 The output compare flag is set at the timer state T11 that follows the comparison match (\$F457 in this example).

Figure 6-4 Timer state timing diagram for output compare



Note: The timer overflow flag is set at timer state T11 (transition of counter from \$FFFF to \$0000). It is cleared by a read of the timer status register during the internal processor clock high time, followed by a read of the counter low register.

Figure 6-5 Timer state timing diagram for timer overflow

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7

DTMF/MELODY GENERATOR

7.1 Introduction

The DTMF/melody generator (DMG) is a multi-functional tone generator built into the MC68HC05F4 MCU which supports DTMF dialling, melody-on-hold and pacifier tone functions.

7

7.1.1 Features

- 4 row and 4 column frequencies for DTMF dialling
- 24 row and 24 column frequencies for dual tone melody
- 28 frequencies for pacifier tone to acknowledge button pressed for pulse dialling
- Power saving mechanism for output disable condition
- 3.579MHz/2 operation
- 6-bit D/A converter and 28 time steps for sine wave generation
- Sine wave or square wave selectable output for melody (or DTMF)
- Single or dual tone capability for melody (or DTMF)

7.2 Functional description

As shown in [Figure 7-1](#), the DMG consists of 2 tone generation paths (the column and row paths). One path generates the row tone and the other the column tone, whose frequencies are determined by the values in the frequency control registers FCR and FCC respectively. The tones allowed at the TNO output are single/dual sine/square wave tones of DTMF and melody frequencies, whereas at the TNX output, only single square wave tones are allowed. The method of tone generation for the two paths is almost the same, and is described as follows.

To generate a sine wave tone with programmable frequency in a path, the internal clock (i.e. the $3.58\text{MHz}/2$) is first divided by a frequency divider according to a number on the register (FCR or FCC). The output of the divider is a periodic pulse train whose frequency is the sampling rate of the desired 'staircase sine wave'. This pulse train, in turn, clocks a divide-by-28 binary counter (PLA scanner) whose 28 decoded outputs scan sequentially 28 memory locations of a 28×6 sine wave generator (PLA) in 28 time steps (M). The six resulting digital sine wave bits are then fed separately to a 6-bit resistor ladder to produce a current signal.

The method for generating a square wave tone in a path is similar to that of a sine wave tone except that only the most significant bit of a sine wave PLA is fed to the 6-bit resistor ladder to produce a current signal (the other 5 least significant bits are masked by the sine/square wave select). Using this method, a square wave tone can be produced which has exactly the same frequency and phase as a sine wave tone, and uses the same frequency control register value.

After obtaining the current signals from the row and column paths, the row current signal is first attenuated by 2dB. It is then summed with the column current signal, and is finally fed to an active 7 KHz low pass filter to reduce harmonic distortion (note that square wave tones are also passed through this filter). The resulting DTMF or melody signal is output through the TNO pin which is normally connected to a speech circuit.

The generator provides not only DTMF and melody but also a square wave pacifier tone (ToneX). This signal is also extracted from the most significant bit of the sine wave PLA of the row path, but is not passed through the filter. The ToneX signal is output through the TNX pin which is normally connected to a loudspeaker.

3.58 MHz/2

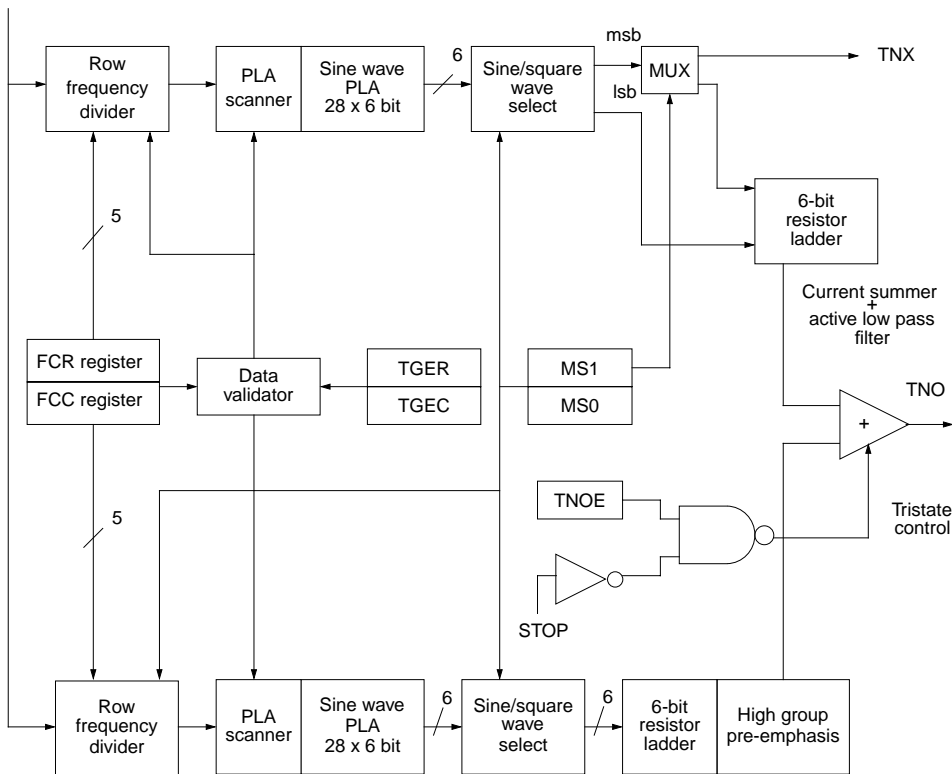


Figure 7-1 DTMF/melody generator (DMG) block diagram

7.3 DMG registers

The DMG has two registers (row frequency control register and column frequency control register) for row and column frequency selection respectively, and one register (tone control register) for tone output control and mode selection.

7.3.1 Row and column frequency control registers

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Row freq. control (FCR)	\$000D	0	0	0	FCR4	FCR3	FCR2	FCR1	FCR0	undefined

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Column freq. control (FCC)	\$000E	0	0	0	FCC4	FCC3	FCC2	FCC1	FCC0	undefined

FCR4–FCR0 and FCC4–FCC0 control the frequency of the tone signals on the row and the column paths respectively. The row and column paths are not exactly identical owing to the presence of the high group pre-emphasis in the column path. In order to avoid the entry of the row DTMF tone values to the column, and vice versa, the above cases are treated as illegal. The data validator will disable all outputs when an illegal value is detected. The bit description for DTMF and melody tone generation are shown in [Table 7-1](#) and [Table 7-2](#) respectively. It is the user's responsibility to ensure good programming practice by initialising all registers to contain legal values for the desired function.

7.3.2 Tone control register (TNCR)

This register controls the internal configuration and tone output timing of the DTMF/melody generator.

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Tone control (TNCR)	\$000F	MS1	MS0	TGER	TGEC	TNOE	0	0	0	0000 0000

MS1, MS0 — Melody select for operation

The MS0 and MS1 bits control the mode of operation of the DTMF/melody generator. There are sine wave, square wave 1, square wave 2 and square wave 3 modes. They are specified as shown in [Table 7-3](#).

When square wave 2 or square wave 3 mode is selected, the TNX pin is activated. The idle state for TNX is a logic high. The final state of the TNX pin is still dependant on the values of TGER, TGEC (see [Table 7-4](#)), FCR and FCC bits (when illegal values are input).

The state of the TNO pin depends on the value of the TNOE bit. After a RESET, the TNOE is cleared and the TNO pin is tristate. When TNOE is set, the TNO output is activated. If the TGER and TGEC bits are held low and TNOE is set, the dc offset of $V_{DD}/2$ appears at TNO pin. In STOP mode, the TNX pin is high and the TNO pin is tristate.

When both MS1 and MS0 are set (square wave 3), the generator can generate both single tone melody at the column path, and ToneX at the row path simultaneously.

TGER — Tone generator enable row path

- 1 (set) – Row path on
- 0 (clear) – Row path off

TGEC — Tone generator enable column path

- 1 (set) – Column path on
- 0 (clear) – Column path off

TNOE — Tone output enable

- 1 (set) – TNO on
- 0 (clear) – TNO off

Table 7-1 Bit description for DTMF generation

FCR register	FCC register	Tone	Standard frequency (Hz)	Tone output frequency (Hz)	Frequency deviation
\$00		f_{R1}	697.0	694.8	-0.32
\$01		f_{R2}	770.0	770.1	0.02
\$02		f_{R3}	852.0	854.2	0.03
\$03		f_{R4}	941.0	940.0	-0.11
	\$10	f_{C1}	1209.0	1206.0	-0.244
	\$11	f_{C2}	1336.0	1331.7	-0.324
	\$12	f_{C3}	1477.0	1486.5	0.645
	\$13	f_{C4}	1633.0	1639.0	0.367

Note: The legal values in the FCR register column are illegal to the FCC register, and vice versa. An input of illegal values to these registers will produce a high at TNX output and $V_{DD}/2$ at TNO output (TNOE = 1)

Table 7-2 Bit description for melody generator

FCR/FCC register	Tone	Standard frequency (Hz)	Tone output frequency (Hz)	Frequency deviation (%)
\$04	D#5	622.3	620.6	-0.28
\$05	E5	659.3	659.0	-0.05
\$06	F5	698.5	694.8	-0.53
\$07	F#5	740.0	743.3	0.44
\$08	G5	784.0	779.5	-0.57
\$09	G#5	830.6	830.1	-0.06
\$0A	A5	880.0	875.6	-0.50
\$0B	A#5	932.0	926.4	-0.64
\$0C	B5	987.8	983.4	-0.45
\$0D	C6	1046.5	1047.9	0.13
\$0E	C#6	1108.7	1102.1	-0.60
\$0F	D6	1174.7	1183.7	0.77
\$14	D#6	1244.5	1253.3	0.71
\$15	E6	1318.5	1331.7	1.00
\$16	F6	1396.9	1389.6	-0.52
\$17	F#6	1480.0	1486.5	0.44
\$18	G6	1568.0	1559.0	-0.57
\$19	G#6	1661.2	1682.1	1.26
\$1A	A6	1760.0	1775.6	0.89
\$1B	A#6	1864.7	1880.0	0.82
\$1C	B6	1975.5	1997.5	1.11
\$1D	C7	2093.0	2062.0	-1.49
\$1E	C#7	2217.5	2204.2	-0.60
\$1F	D7	2349.3	2367.4	0.771

Table 7-3 Mode of operation for DMG

MS1	MS0	Mode	TNX output	TNO output
0	0	sine wave	high	sine wave row and column frequency
0	1	square wave 1	high	square wave row and column frequency
1	0	square wave 2	row frequency	square wave row and column frequency
1	1	square wave 3	row frequency	square wave column frequency

TGER, TGEC — Tone generation enable for row and column paths

When both bits are held low, the DMG is disabled by forcing the two frequency counters and the two PLA scanning counters to their reset states. The DMG should then consume zero dynamic power, if the TNOE bit is also cleared.

When a TGE bit for a path is held high (provided that the value in the frequency control register for that path is legal), the generator is enabled. All the counters associated with that path are then run from their reset states.

The reset state of a frequency counter defines the time=0 state of the time step, whereas at their reset state, the PLA scanning counters, scanning the memory location, contain the dc values of the staircase sine wave.

In DTMF dialling, the row and column tone values are first entered to the FCR and FCC registers. The TGER and TGEC bits are then set or reset simultaneously to achieve dual tone multiple frequency. Similarly, in melody generation, one path is chosen as the high part, and the other as the low part. The TGER and TGEC bits are then set and reset according to the rhythm required by the musical piece. One can exhibit only single tone melody by disabling either TGER or TGEC permanently. The DTMF column and row frequency tones can also be output separately for testing by enabling just the one path.

Table 7-4 Effect of tone generation on DMG

TGER	TGEC	Row Path	Column Path
0	0	off	off
0	1	off	active
1	0	active	off
1	1	active	active

7.4 Operation of the DMG

The DMG is recommended to be operated using the following procedures:

To operate melody generation, the choice of sine wave or square wave output mode is totally up to the user's taste. The sine wave melody has a sound like a flute, whereas the square wave melody possesses much richer harmonics. The required tones are selected through the FCR and FCC registers. The selected tone is output when the corresponding TGER or TGEC bit and TNOE bit are set. The FCR register should contain the value representing the tone output frequency and the FCC register should contain a value of \$04 or greater to ensure the output is not blocked by the data validator.

7.5 DMG during WAIT mode

The DMG is still active during the WAIT mode.

7.6 DMG during STOP mode

In STOP mode the oscillator is stopped causing the DMG to cease function.

8

RESETS AND INTERRUPTS

8.1 Resets

The MC68HC05F4 can be reset in five ways: by the initial power-on reset function, by an active low input to the $\overline{\text{RESET}}$ pin, by an on-chip low voltage reset, by an opcode fetch from an illegal address, and by a COP watchdog timer reset. Any of these resets will cause the program to return to its starting address, specified by the contents of memory locations \$3FFE and \$3FFF, and cause the interrupt mask of the CCR to be set.

8

8.1.1 Power-on reset

A power-on reset occurs when a positive transition is detected on VDD. The power-on reset function is strictly for power turn-on conditions and should not be used to detect drops in the power supply voltage. The power-on circuitry provides a stabilization delay (t_{PORL}) from when the oscillator becomes active. If the external $\overline{\text{RESET}}$ pin is low at the end of this delay then the processor remains in the reset state until $\overline{\text{RESET}}$ goes high.

8.1.2 $\overline{\text{RESET}}$ pin

When the oscillator is running in a stable state, the MCU is reset when a logic zero is applied to the $\overline{\text{RESET}}$ input for a minimum period of 1.5 machine cycles (t_{CYC}). This pin contains an internal Schmitt trigger as part of its input to improve noise immunity. When the reset pin goes high, the MCU will resume operation on the following cycle. The $\overline{\text{RESET}}$ pin is also an output device for the internal low voltage reset.

8.1.3 Illegal address reset

When an opcode fetch occurs from an address which is not part of the RAM (\$0040 – \$013F) or of the ROM (\$3000 – \$3FFF) or EEPROM (\$0200 – \$02FF), the device is automatically reset.

Note: No RTS or RTI instruction should be placed at the end of a memory block since this could result in an illegal address reset.

8.1.4 Computer operating properly (COP) reset

The MCU contains a watchdog timer that automatically times out if not reset (cleared) within a specific time by a program reset sequence.

If the COP watchdog timer is allowed to timeout, an internal reset is generated to reset the MCU. Because the internal reset signal is used, the MCU comes out of a COP reset in the same operating mode it was in when the COP timeout was generated.

The COP function is a mask option, enabled or disabled during device manufacture. See [Section 1.2](#).

Refer to [Section 5.3](#) for more information on the COP watchdog timer.

8.1.5 Low voltage reset

The MCU contains a low voltage detection circuit which drives the external reset.

For a positive transition of supply voltage V_{DD} , the low voltage reset occurs as long as V_{DD} is below the V_{RON} level. In this case the external reset pin is pulled down. If the supply voltage drops off above the V_{RON} level, the reset is released. If the supply voltage falls off below the V_{ROFF} level, the \overline{RESET} pin is pulled down.

8.2 Interrupts

The MCU can be interrupted by six different sources, five maskable hardware interrupts and one nonmaskable software interrupt:

- External signal on the $\overline{\text{IRQ}}$ pin
- Keyboard interrupt
- Core timer interrupt
- 16-bit programmable timer interrupt
- Low voltage interrupt (LVI) – EEPROM
- Software interrupt instruction (SWI)

Interrupts cause the processor to save the register contents on the stack and to set the interrupt mask (I-bit) to prevent additional interrupts. The RTI instruction (return from interrupt) causes the register contents to be recovered from the stack and normal processing to resume. While executing the RTI instruction, the interrupt mask bit (I-bit) will be cleared providing the corresponding enable bit stored on the stack is zero, i.e. the interrupt is disabled.

Unlike reset, hardware interrupts do not cause the current instruction execution to be halted, but are considered pending until the current instruction is complete. The current instruction is the one already fetched and being operated on. When the current instruction is complete, the processor checks all pending hardware interrupts. If interrupts are not masked (CCR I-bit clear) and the corresponding interrupt enable bit is set, the processor proceeds with interrupt processing; otherwise, the next instruction is fetched and executed. [Figure 8-1](#) shows the interrupt processing flow.

Note: Power-on or external reset clears all interrupt enable bits thus preventing interrupts during the reset sequence.

8.2.1 Interrupt priorities

Each potential interrupt source is assigned a priority which means that if more than one interrupt is pending at the same time, the processor will service the one with the highest priority first. For example, if both an external interrupt and a timer interrupt are pending after an instruction execution, the external interrupt is serviced first.

8.2.2 Non-maskable software interrupt (SWI)

The software interrupt (SWI) is an executable instruction and a nonmaskable interrupt: it is executed regardless of the state of the I-bit in the CCR. If the I-bit is zero (interrupts enabled), SWI is executed after interrupts that were pending when the SWI was fetched, but before interrupts generated after the SWI was fetched. The SWI interrupt service routine address is specified by the contents of memory locations \$3FFC and \$3FFD.

8

8.2.3 Maskable hardware interrupts

If the interrupt mask bit (I-bit) of the CCR is set, all maskable interrupts (internal and external) are masked. Clearing the I-bit allows interrupt processing to occur. $\overline{\text{IRQ}}$ is software selectable as either edge or edge-and-level sensitive (bit 3 of the system option register).

Note: The internal interrupt latch is cleared in the first part of the interrupt service routine; therefore, one external interrupt pulse could be latched and serviced as soon as the I-bit is cleared.

8.2.3.1 Real time and core timer (CTIMER) interrupts

There are two different core timer interrupt flags that cause a CTIMER interrupt whenever an interrupt is enabled and its flag becomes set, namely RTIF and CTOF. The interrupt flags and enable bits are located in the CTIMER control and status register (CTCSR). These interrupts will vector to the same interrupt service routine, whose start address is contained in memory locations \$3FF8 and \$3FF9 (see [Section 5.2.1](#) and [Figure 5-1](#)).

To make use of the real time interrupt the RTIE bit must first be set. The RTIF bit will then be set after the specified number of counts.

To make use of the core timer overflow interrupt, the CTOFE bit must first be set. The CTOF bit will then be set when the core timer counter register overflows from \$FF to \$00.

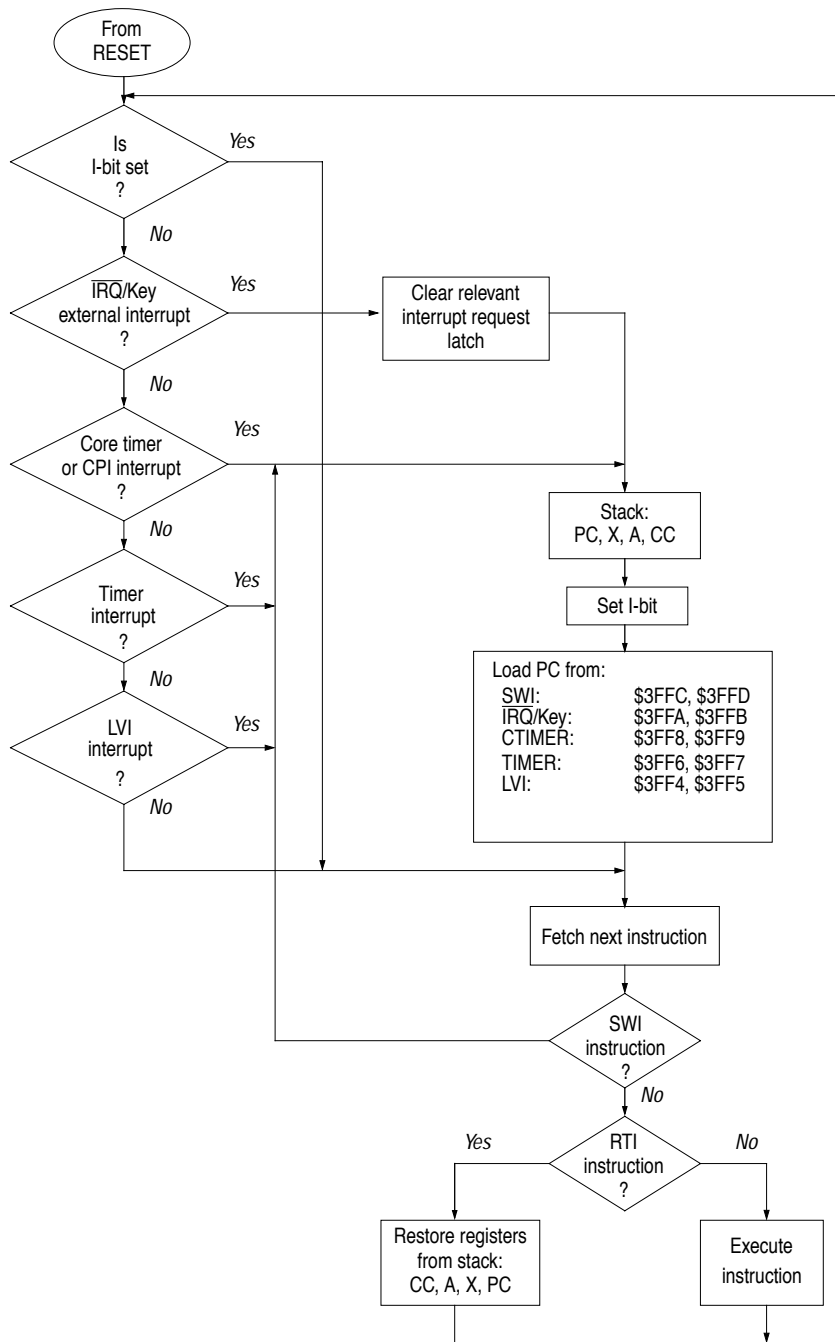


Figure 8-1 Interrupt flowchart

Table 8-1 Vector address for interrupts and reset

Register	Flag name	Interrupts	CPU interrupt	Vector address
—	—	Reset	RESET	\$3FFE–\$3FFF
—	—	Software interrupt	SWI	\$3FFC–\$3FFD
—	—	External interrupt	IRQ	\$3FFA–\$3FFB
CTCSR	CTOF	Core timer overflow	CTIMER	\$3FF8–\$3FF9
CTCSR	RTIF	Real time interrupt	CTIMER	\$3FF8–\$3FF9
TSR	IC1F	Timer input capture1	TIMER	\$3FF6–\$3FF7
TSR	OC1F	Timer output compare1	TIMER	\$3FF6–\$3FF7
TSR	IC2F	Timer input capture2	TIMER	\$3FF6–\$3FF7
TSR	OC2F	Timer output compare2	TIMER	\$3FF6–\$3FF7
TSR	TOF	Timer overflow	TIMER	\$3FF6–\$3FF7
KCR	KF	Keyboard interrupt	KEYF	\$3FFA–\$3FFB
SOR	LVIF	Low voltage interrupt	LVI	\$3FF4–\$3FF5

8

8.2.3.2 Programmable 16-bit timer interrupt

There are five different timer interrupt flags that cause a timer interrupt whenever they are set and enabled. The timer interrupt enable bits are located in the timer control register (TCR) and the timer interrupt flags are located in the timer status register (TSR). Both interrupts will vector to the same service routine, whose start address is contained in memory locations \$3FF6 and \$3FF7.

8.2.3.3 Keyboard interrupt

When configured as input pins, all eight port A lines provide a wired-OR keyboard interrupt facility and will generate an interrupt, provided that the keyboard interrupt enable bit (KIE) in the key control register (KCR) is set. The address of the interrupt service routine is specified by the contents of memory locations \$3FFA and \$3FFB. Since this interrupt vector is shared with the IRQ external interrupt function the interrupt service routine should check KF to determine the interrupt source. KF should be cleared by software in the interrupt service routine. Care must be taken to allow adequate time for switch debounce before clearing the flag.

8.2.3.4 Low voltage interrupt

There is a low voltage interrupt flag that causes an interrupt whenever it is set and enabled. The low voltage interrupt enable bit and the interrupt flag are located in the system option register (SOR) described below in [Section 8.2.3.5](#). This interrupt will vector to the service routine, located at the address specified by the contents of memory locations \$3FF4 and \$3FF5.

8.2.3.5 System options register

The MC68HC05F4 MCU contains a system options register which is located at address \$11. This register is used to control the LVI and the clock system.

Note: The LVI uses the voltage reference of the low voltage reset (LVR) circuitry. This means that the LVI can only be used if the LVR is enabled by mask option.

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
System options register (SOR)	\$0011	LVIF	LVIE	LVION	SC	IRQ	0	0	0	0000 0000

LVIF — Low voltage interrupt flag

- 1 (set) – A low voltage interrupt has occurred.
- 0 (clear) – No low voltage interrupt has occurred.

LVIF is a read only status bit and is set by the low voltage detection circuit, if power supply VDD falls below V_{LVi} , provided the LVR is enabled (mask option) and the LVION and LVIE bits are set. The LVIF flag is reset by clearing the LVIE bit. The LVI circuit is rearmed by again setting the LVIE bit.

LVIE — Low voltage interrupt enable

- 1 (set) – Low voltage interrupt and flag generation is enabled.
- 0 (clear) – Low voltage interrupt and flag generation is disabled.

Setting this bit enables the low voltage flag and interrupt generation. A CPU interrupt request will then be generated whenever the LVIF bit becomes set and the I-bit in the CCR is clear.

LVION — Low voltage interrupt on

- 1 (set) – Power is supplied to the LVI circuitry.
- 0 (clear) – LVI circuitry is disconnected from the power supply.

Setting this bit applies power to the LVI circuitry. If the LVI function is not used this bit should be cleared to save power.

Note: This bit must be set at least one instruction cycle before setting the LVIE bit, to give the LVI circuitry time to stabilize.

For descriptions of bits SC and IRQ see [Section 2.3](#).

8.2.4 Hardware controlled interrupt sequence

The following three functions (RESET, STOP, and WAIT) are not in the strictest sense interrupts. However, they are acted upon in a similar manner. Flowcharts for STOP and WAIT are shown in [Figure 2-1](#).

RESET: A reset condition causes the program to vector to its starting address, which is contained in memory locations \$3FFE (MSB) and \$3FFF (LSB). The I-bit in the condition code register is also set, to disable interrupts.

STOP: The STOP instruction causes the oscillator to be turned off and the processor to 'sleep' until an external interrupt ($\overline{\text{IRQ}}$), a low voltage interrupt (LVI) or a keyboard interrupt occurs, or the device is reset.

WAIT: The WAIT instruction causes all processor clocks to stop, but leaves the timer clocks running. This 'rest' state of the processor can be cleared by reset, an external interrupt ($\overline{\text{IRQ}}$), a keyboard interrupt, a timer interrupt (core or 16-bit) or an LVI interrupt. There are no special WAIT vectors for these interrupts.

9

CPU CORE AND INSTRUCTION SET

This section provides a description of the CPU core registers, the instruction set and the addressing modes of the MC68HC05F4.

9.1 Registers

The MCU contains five registers, as shown in the programming model of Figure 9-1. The interrupt stacking order is shown in Figure 9-2.

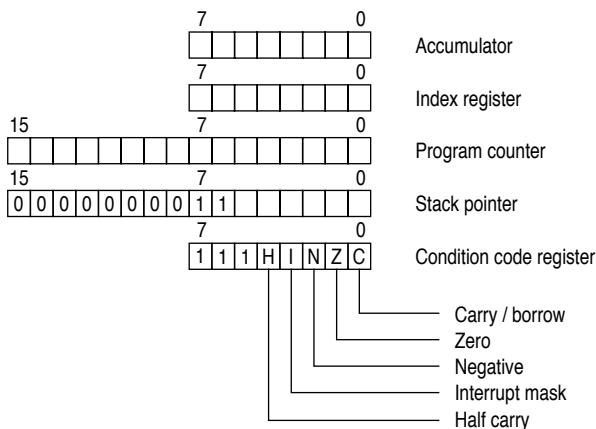


Figure 9-1 Programming model

9.1.1 Accumulator (A)

The accumulator is a general purpose 8-bit register used to hold operands and results of arithmetic calculations or data manipulations.

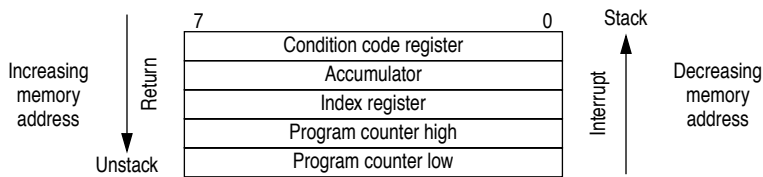


Figure 9-2 Stacking order

9.1.2 Index register (X)

The index register is an 8-bit register, which can contain the indexed addressing value used to create an effective address. The index register may also be used as a temporary storage area.

9.1.3 Program counter (PC)

The program counter is a 16-bit register, which contains the address of the next byte to be fetched.

9

9.1.4 Stack pointer (SP)

The stack pointer is a 16-bit register, which contains the address of the next free location on the stack. During an MCU reset or the reset stack pointer (RSP) instruction, the stack pointer is set to location \$00FF. The stack pointer is then decremented as data is pushed onto the stack and incremented as data is pulled from the stack.

When accessing memory, the ten most significant bits are permanently set to 000000011. These ten bits are appended to the six least significant register bits to produce an address within the range of \$00C0 to \$00FF. Subroutines and interrupts may use up to 64 (decimal) locations. If 64 locations are exceeded, the stack pointer wraps around and overwrites the previously stored information. A subroutine call occupies two locations on the stack; an interrupt uses five locations.

9.1.5 Condition code register (CCR)

The CCR is a 5-bit register in which four bits are used to indicate the results of the instruction just executed, and the fifth bit indicates whether interrupts are masked. These bits can be individually tested by a program, and specific actions can be taken as a result of their state. Each bit is explained in the following paragraphs.

Half carry (H)

This bit is set during ADD and ADC operations to indicate that a carry occurred between bits 3 and 4.

Interrupt (I)

When this bit is set, all maskable interrupts are masked. If an interrupt occurs while this bit is set, the interrupt is latched and remains pending until the interrupt bit is cleared.

Negative (N)

When set, this bit indicates that the result of the last arithmetic, logical, or data manipulation was negative.

Zero (Z)

When set, this bit indicates that the result of the last arithmetic, logical, or data manipulation was zero.

Carry/borrow (C)

When set, this bit indicates that a carry or borrow out of the arithmetic logical unit (ALU) occurred during the last arithmetic operation. This bit is also affected during bit test and branch instructions and during shifts and rotates.

9.2 Instruction set

The MCU has a set of 62 basic instructions. They can be grouped into five different types as follows:

- Register/memory
- Read/modify/write
- Branch
- Bit manipulation
- Control

The following paragraphs briefly explain each type. All the instructions within a given type are presented in individual tables.

This MCU uses all the instructions available in the M146805 CMOS family plus one more: the unsigned multiply (MUL) instruction. This instruction allows unsigned multiplication of the contents of the accumulator (A) and the index register (X). The high-order product is then stored in the index register and the low-order product is stored in the accumulator. A detailed definition of the MUL instruction is shown in [Table 9-1](#).

9.2.1 Register/memory Instructions

Most of these instructions use two operands. The first operand is either the accumulator or the index register. The second operand is obtained from memory using one of the addressing modes. The jump unconditional (JMP) and jump to subroutine (JSR) instructions have no register operand. Refer to [Table 9-2](#) for a complete list of register/memory instructions.

9.2.2 Branch instructions

These instructions cause the program to branch if a particular condition is met; otherwise, no operation is performed. Branch instructions are two-byte instructions. Refer to [Table 9-3](#).

9.2.3 Bit manipulation instructions

The MCU can set or clear any writable bit that resides in the first 256 bytes of the memory space (page 0). All port data and data direction registers, timer and serial interface registers, control/status registers and a portion of the on-chip RAM reside in page 0. An additional feature allows the software to test and branch on the state of any bit within these locations. The bit set, bit clear, bit test and branch functions are all implemented with single instructions. For the test and branch instructions, the value of the bit tested is also placed in the carry bit of the condition code register. Refer to [Table 9-4](#).

9.2.4 Read/modify/write instructions

These instructions read a memory location or a register, modify or test its contents, and write the modified value back to memory or to the register. The test for negative or zero (TST) instruction is an exception to this sequence of reading, modifying and writing, since it does not modify the value. Refer to [Table 9-5](#) for a complete list of read/modify/write instructions.

9.2.5 Control instructions

These instructions are register reference instructions and are used to control processor operation during program execution. Refer to [Table 9-6](#) for a complete list of control instructions.

9.2.6 Tables

Tables for all the instruction types listed above follow. In addition there is a complete alphabetical listing of all the instructions (see [Table 9-7](#)), and an opcode map for the instruction set of the M68HC05 MCU family (see [Table 9-8](#)).

Table 9-1 MUL instruction

Operation	$X:A \leftarrow X * A$			
Description	Multiplies the eight bits in the index register by the eight bits in the accumulator and places the 16-bit result in the concatenated accumulator and index register.			
Condition codes	H : Cleared I : Not affected N : Not affected Z : Not affected C : Cleared			
Source	MUL			
Form	Addressing mode Inherent	Cycles 11	Bytes 1	Opcode \$42

9.3 Addressing modes

Ten different addressing modes provide programmers with the flexibility to optimize their code for all situations. The various indexed addressing modes make it possible to locate data tables, code conversion tables and scaling tables anywhere in the memory space. Short indexed accesses are single byte instructions; the longest instructions (three bytes) enable access to tables throughout memory. Short absolute (direct) and long absolute (extended) addressing are also included. One or two byte direct addressing instructions access all data bytes in most applications. Extended addressing permits jump instructions to reach all memory locations.

The term 'effective address' (EA) is used in describing the various addressing modes. The effective address is defined as the address from which the argument for an instruction is fetched or stored. The ten addressing modes of the processor are described below. Parentheses are used to indicate 'contents of' the location or register referred to. For example, (PC) indicates the contents of the location pointed to by the PC (program counter). An arrow indicates 'is replaced by' and a colon indicates concatenation of two bytes. For additional details and graphical illustrations, refer to the *M6805 HMOS/M146805 CMOS Family Microcomputer/ Microprocessor User's Manual* or to the *M68HC05 Applications Guide*.

Table 9-2 Register/memory instructions

Function	Mnemonic	Addressing modes																	
		Immediate			Direct			Extended			Indexed (no offset)			Indexed (8-bit offset)			Indexed (16-bit offset)		
		Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles
Load A from memory	LDA	A6	2	2	B6	2	3	C6	3	4	F6	1	3	E6	2	4	D6	3	5
Load X from memory	LDX	AE	2	2	BE	2	3	CE	3	4	FE	1	3	EE	2	4	DE	3	5
Store A in memory	STA				B7	2	4	C7	3	5	F7	1	4	E7	2	5	D7	3	6
Store X in memory	STX				BF	2	4	CF	3	5	FF	1	4	EF	2	5	DF	3	6
Add memory to A	ADD	AB	2	2	BB	2	3	CB	3	4	FB	1	3	EB	2	4	DB	3	5
Add memory and carry to A	ADC	A9	2	2	B9	2	3	C9	3	4	F9	1	3	E9	2	4	D9	3	5
Subtract memory	SUB	A0	2	2	B0	2	3	C0	3	4	F0	1	3	E0	2	4	D0	3	5
Subtract memory from A with borrow	SBC	A2	2	2	B2	2	3	C2	3	4	F2	1	3	E2	2	4	D2	3	5
AND memory with A	AND	A4	2	2	B4	2	3	C4	3	4	F4	1	3	E4	2	4	D4	3	5
OR memory with A	ORA	AA	2	2	BA	2	3	CA	3	4	FA	1	3	EA	2	4	DA	3	5
Exclusive OR memory with A	EOR	A8	2	2	B8	2	3	C8	3	4	F8	1	3	E8	2	4	D8	3	5
Arithmetic compare A with memory	CMP	A1	2	2	B1	2	3	C1	3	4	F1	1	3	E1	2	4	D1	3	5
Arithmetic compare X with memory	CPX	A3	2	2	B3	2	3	C3	3	4	F3	1	3	E3	2	4	D3	3	5
Bit test memory with A (logical compare)	BIT	A5	2	2	B5	2	3	C5	3	4	F5	1	3	E5	2	4	D5	3	5
Jump unconditional	JMP				BC	2	2	CC	3	3	FC	1	2	EC	2	3	DC	3	4
Jump to subroutine	JSR				BD	2	5	CD	3	6	FD	1	5	ED	2	6	DD	3	7

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9.3.1 Inherent

In the inherent addressing mode, all the information necessary to execute the instruction is contained in the opcode. Operations specifying only the index register or accumulator, as well as the control instruction, with no other arguments are included in this mode. These instructions are one byte long.

9.3.2 Immediate

In the immediate addressing mode, the operand is contained in the byte immediately following the opcode. The immediate addressing mode is used to access constants that do not change during program execution (e.g. a constant used to initialize a loop counter).

$$EA = PC+1; PC \leftarrow PC+2$$

Table 9-3 Branch instructions

Function	Mnemonic	Relative addressing mode		
		Opcode	# Bytes	# Cycles
Branch always	BRA	20	2	3
Branch never	BRN	21	2	3
Branch if higher	BHI	22	2	3
Branch if lower or same	BLS	23	2	3
Branch if carry clear	BCC	24	2	3
(Branch if higher or same)	(BHS)	24	2	3
Branch if carry set	BCS	25	2	3
(Branch if lower)	(BLO)	25	2	3
Branch if not equal	BNE	26	2	3
Branch if equal	BEQ	27	2	3
Branch if half carry clear	BHCC	28	2	3
Branch if half carry set	BHCS	29	2	3
Branch if plus	BPL	2A	2	3
Branch if minus	BMI	2B	2	3
Branch if interrupt mask bit is clear	BMC	2C	2	3
Branch if interrupt mask bit is set	BMS	2D	2	3
Branch if interrupt line is low	BIL	2E	2	3
Branch if interrupt line is high	BIH	2F	2	3
Branch to subroutine	BSR	AD	2	6

Table 9-4 Bit manipulation instructions

Function	Mnemonic	Addressing modes					
		Bit set/clear			Bit test and branch		
		Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles
Branch if bit n is set	BRSET n (n=0-7)				2*n	3	5
Branch if bit n is clear	BRCLR n (n=0-7)				01+2*n	3	5
Set bit n	BSET n (n=0-7)	10+2*n	2	5			
Clear bit n	BCLR n (n=0-7)	11+2*n	2	5			

9.3.3 Direct

In the direct addressing mode, the effective address of the argument is contained in a single byte following the opcode byte. Direct addressing allows the user to directly address the lowest 256 bytes in memory with a single two-byte instruction.

$$EA = (PC+1); PC \leftarrow PC+2$$

$$\text{Address bus high} \leftarrow 0; \text{Address bus low} \leftarrow (PC+1)$$

Table 9-5 Read/modify/write instructions

Function	Mnemonic	Addressing modes														
		Inherent (A)			Inherent (X)			Direct			Indexed (no offset)			Indexed (8-bit offset)		
		Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles
Increment	INC	4C	1	3	5C	1	3	3C	2	5	7C	1	5	6C	2	6
Decrement	DEC	4A	1	3	5A	1	3	3A	2	5	7A	1	5	6A	2	6
Clear	CLR	4F	1	3	5F	1	3	3F	2	5	7F	1	5	6F	2	6
Complement	COM	43	1	3	53	1	3	33	2	5	73	1	5	63	2	6
Negate (two's complement)	NEG	40	1	3	50	1	3	30	2	5	70	1	5	60	2	6
Rotate left through carry	ROL	49	1	3	59	1	3	39	2	5	79	1	5	69	2	6
Rotate right through carry	ROR	46	1	3	56	1	3	36	2	5	76	1	5	66	2	6
Logical shift left	LSL	48	1	3	58	1	3	38	2	5	78	1	5	68	2	6
Logical shift right	LSR	44	1	3	54	1	3	34	2	5	74	1	5	64	2	6
Arithmetic shift right	ASR	47	1	3	57	1	3	37	2	5	77	1	5	67	2	6
Test for negative or zero	TST	4D	1	3	5D	1	3	3D	2	4	7D	1	4	6D	2	5
Multiply	MUL	42	1	11												

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Table 9-6 Control instructions

Function	Mnemonic	Inherent addressing mode		
		Opcode	# Bytes	# Cycles
Transfer A to X	TAX	97	1	2
Transfer X to A	TXA	9F	1	2
Set carry bit	SEC	99	1	2
Clear carry bit	CLC	98	1	2
Set interrupt mask bit	SEI	9B	1	2
Clear interrupt mask bit	CLI	9A	1	2
Software interrupt	SWI	83	1	10
Return from subroutine	RTS	81	1	6
Return from interrupt	RTI	80	1	9
Reset stack pointer	RSP	9C	1	2
No-operation	NOP	9D	1	2
Stop	STOP	8E	1	2
Wait	WAIT	8F	1	2

Table 9-7 Instruction set

Mnemonic	Addressing modes										Condition codes				
	INH	IMM	DIR	EXT	REL	IX	IX1	IX2	BSC	BTB	H	I	N	Z	C
ADC											◇	•	◇	◇	◇
ADD											◇	•	◇	◇	◇
AND											•	•	◇	◇	•
ASL											•	•	◇	◇	◇
ASR											•	•	◇	◇	◇
BCC											•	•	•	•	•
BCLR											•	•	•	•	•
BCS											•	•	•	•	•
BEQ											•	•	•	•	•
BHCC											•	•	•	•	•
BHCS											•	•	•	•	•
BHI											•	•	•	•	•
BHS											•	•	•	•	•
BIH											•	•	•	•	•
BIL											•	•	•	•	•
BIT											•	•	◇	◇	•
BLO											•	•	•	•	•
BLS											•	•	•	•	•
BMC											•	•	•	•	•
BMI											•	•	•	•	•
BMS											•	•	•	•	•
BNE											•	•	•	•	•
BPL											•	•	•	•	•
BRA											•	•	•	•	•
BRN											•	•	•	•	•
BRCLR											•	•	•	•	◇
BRSET											•	•	•	•	◇
BSET											•	•	•	•	•
BSR											•	•	•	•	•
CLC											•	•	•	•	0
CLI											•	0	•	•	•
CLR											•	•	0	1	•
CMP											•	•	◇	◇	◇

Address mode abbreviations

BSC	Bit set/clear	IMM	Immediate
BTB	Bit test & branch	IX	Indexed (no offset)
DIR	Direct	IX1	Indexed, 1 byte offset
EXT	Extended	IX2	Indexed, 2 byte offset
INH	Inherent	REL	Relative

Not implemented

Condition code symbols

H	Half carry (from bit 3)	◇	Tested and set if true, cleared otherwise
I	Interrupt mask	•	Not affected
N	Negate (sign bit)	?	Load CCR from stack
Z	Zero	0	Cleared
C	Carry/borrow	1	Set

Table 9-7 Instruction set (Continued)

Mnemonic	Addressing modes										Condition codes				
	INH	IMM	DIR	EXT	REL	IX	IX1	IX2	BSC	BTB	H	I	N	Z	C
COM											•	•	◊	◊	1
CPX											•	•	◊	◊	◊
DEC											•	•	◊	◊	•
EOR											•	•	◊	◊	•
INC											•	•	◊	◊	•
JMP											•	•	•	•	•
JSR											•	•	•	•	•
LDA											•	•	◊	◊	•
LDX											•	•	◊	◊	•
LSL											•	•	◊	◊	◊
LSR											•	•	0	◊	◊
MUL											0	•	•	•	0
NEG											•	•	◊	◊	◊
NOP											•	•	•	•	•
ORA											•	•	◊	◊	•
ROL											•	•	◊	◊	◊
ROR											•	•	◊	◊	◊
RSP											•	•	•	•	•
RTI											?	?	?	?	?
RTS											•	•	•	•	•
SBC											•	•	◊	◊	◊
SEC											•	•	•	•	1
SEI											•	1	•	•	•
STA											•	•	◊	◊	•
STOP											•	0	•	•	•
STX											•	•	◊	◊	•
SUB											•	•	◊	◊	◊
SWI											•	1	•	•	•
TAX											•	•	•	•	•
TST											•	•	◊	◊	•
TXA											•	•	•	•	•
WAIT											•	0	•	•	•

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Address mode abbreviations

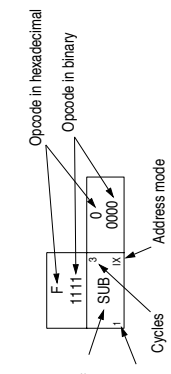
BSC	Bit set/clear	IMM	Immediate
BTB	Bit test & branch	IX	Indexed (no offset)
DIR	Direct	IX1	Indexed, 1 byte offset
EXT	Extended	IX2	Indexed, 2 byte offset
INH	Inherent	REL	Relative
		Not implemented	

Condition code symbols

H	Half carry (from bit 3)	◊	Tested and set if true, cleared otherwise
I	Interrupt mask	•	Not affected
N	Negate (sign bit)	?	Load CCR from stack
Z	Zero	0	Cleared
C	Carry/borrow	1	Set

Table 9-8 M68HC05 opcode map

High Low	Bit manipulation			Read/modify/write					Control			Register/memory					
	BTB	BSC	REL	DIR	INH	INH	IX1	IX	INH	INH	IMM	DIR	EXT	IX2	IX1	IX	
0	0000	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F	
0000	BSET0 ⁵ _{BTB}	BSET0 ⁵ _{BSC}	BRA ³ _{REL}	NEG ⁵ _{DIR}	NEGA ³ _{INH}	NEGB ³ _{INH}	NEG ⁶ _{IX1}	NEG ⁵ _{IX}	RTI ⁹ _{INH}		SUB ² _{MM}	SUB ³ _{DIR}	SUB ⁴ _{EXT}	SUB ⁵ _{IX2}	SUB ⁴ _{IX1}	SUB ³ _{IX}	
0001	BCLR0 ⁵ _{BTB}	BCLR0 ⁵ _{BSC}	BRN ³ _{REL}						RTS ⁶ _{INH}		CMP ² _{MM}	CMP ³ _{DIR}	CMP ⁴ _{EXT}	CMP ⁵ _{IX2}	CMP ⁴ _{IX1}	CMP ³ _{IX}	
0010	BSET1 ⁵ _{BTB}	BSET1 ⁵ _{BSC}	BHI ³ _{REL}		MUL ¹¹ _{INH}						SBC ² _{MM}	SBC ³ _{DIR}	SBC ⁴ _{EXT}	SBC ⁵ _{IX2}	SBC ⁴ _{IX1}	SBC ³ _{IX}	
0011	BCLR1 ⁵ _{BTB}	BCLR1 ⁵ _{BSC}	BLS ³ _{REL}	COM ⁵ _{DIR}	COMA ³ _{INH}	COMB ³ _{INH}	COM ⁶ _{IX1}	COM ⁵ _{IX}	SWI ¹⁰ _{INH}		CPX ² _{MM}	CPX ³ _{DIR}	CPX ⁴ _{EXT}	CPX ⁵ _{IX2}	CPX ⁴ _{IX1}	CPX ³ _{IX}	
0100	BSET2 ⁵ _{BTB}	BSET2 ⁵ _{BSC}	BCC ³ _{REL}	LSR ³ _{DIR}	LSRA ³ _{INH}	LSRB ³ _{INH}	LSR ⁶ _{IX1}	LSR ⁵ _{IX}			AND ² _{MM}	AND ³ _{DIR}	AND ⁴ _{EXT}	AND ⁵ _{IX2}	AND ⁴ _{IX1}	AND ³ _{IX}	
0101	BCLR2 ⁵ _{BTB}	BCLR2 ⁵ _{BSC}	BCS ³ _{REL}								BIT ² _{MM}	BIT ³ _{DIR}	BIT ⁴ _{EXT}	BIT ⁵ _{IX2}	BIT ⁴ _{IX1}	BIT ³ _{IX}	
0110	BSET3 ⁵ _{BTB}	BSET3 ⁵ _{BSC}	BNE ³ _{REL}	ROR ⁵ _{DIR}	RORA ³ _{INH}	RORX ³ _{INH}	ROR ⁶ _{IX1}	ROR ⁵ _{IX}			LDA ² _{MM}	LDA ³ _{DIR}	LDA ⁴ _{EXT}	LDA ⁵ _{IX2}	LDA ⁴ _{IX1}	LDA ³ _{IX}	
0111	BCLR3 ⁵ _{BTB}	BCLR3 ⁵ _{BSC}	BEQ ³ _{REL}	ASR ³ _{DIR}	ASRA ³ _{INH}	ASRX ³ _{INH}	ASR ⁶ _{IX1}	ASR ⁵ _{IX}	TAX ¹ _{INH}		STA ² _{MM}	STA ³ _{DIR}	STA ⁴ _{EXT}	STA ⁵ _{IX2}	STA ⁴ _{IX1}	STA ³ _{IX}	
1000	BSET4 ⁵ _{BTB}	BSET4 ⁵ _{BSC}	BHCS ³ _{REL}	LSL ⁵ _{DIR}	LSLA ³ _{INH}	LSLX ³ _{INH}	LSL ⁶ _{IX1}	LSL ⁵ _{IX}			EOR ² _{MM}	EOR ³ _{DIR}	EOR ⁴ _{EXT}	EOR ⁵ _{IX2}	EOR ⁴ _{IX1}	EOR ³ _{IX}	
1001	BCLR4 ⁵ _{BTB}	BCLR4 ⁵ _{BSC}	BHCS ³ _{REL}	ROL ⁵ _{DIR}	ROLA ³ _{INH}	ROLX ³ _{INH}	ROL ⁶ _{IX1}	ROL ⁵ _{IX}			ADC ² _{MM}	ADC ³ _{DIR}	ADC ⁴ _{EXT}	ADC ⁵ _{IX2}	ADC ⁴ _{IX1}	ADC ³ _{IX}	
A	BSET5 ⁵ _{BTB}	BSET5 ⁵ _{BSC}	BPL ³ _{REL}	DEC ³ _{DIR}	DECA ³ _{INH}	DECX ³ _{INH}	DEC ⁶ _{IX1}	DEC ⁵ _{IX}			ORA ² _{MM}	ORA ³ _{DIR}	ORA ⁴ _{EXT}	ORA ⁵ _{IX2}	ORA ⁴ _{IX1}	ORA ³ _{IX}	
B	BCLR5 ⁵ _{BTB}	BCLR5 ⁵ _{BSC}	BMI ³ _{REL}								SEI ² _{MM}	ADD ³ _{DIR}	ADD ⁴ _{EXT}	ADD ⁵ _{IX2}	ADD ⁴ _{IX1}	ADD ³ _{IX}	
C	BSET6 ⁵ _{BTB}	BSET6 ⁵ _{BSC}	BMC ³ _{REL}	INC ³ _{DIR}	INCA ³ _{INH}	INCX ³ _{INH}	INC ⁶ _{IX1}	INC ⁵ _{IX}			RSP ² _{MM}	JMP ³ _{DIR}	JMP ⁴ _{EXT}	JMP ⁵ _{IX2}	JMP ⁴ _{IX1}	JMP ³ _{IX}	
D	BCLR6 ⁵ _{BTB}	BCLR6 ⁵ _{BSC}	BMS ³ _{REL}	TST ³ _{DIR}	TSTA ³ _{INH}	TSTX ³ _{INH}	TST ⁶ _{IX1}	TST ⁵ _{IX}		BSR ² _{MM}	JSR ³ _{DIR}	JSR ⁴ _{EXT}	JSR ⁵ _{IX2}	JSR ⁴ _{IX1}	JSR ³ _{IX}		
E	BSET7 ⁵ _{BTB}	BSET7 ⁵ _{BSC}	BIL ³ _{REL}						STOP ² _{INH}		LDX ² _{MM}	LDX ³ _{DIR}	LDX ⁴ _{EXT}	LDX ⁵ _{IX2}	LDX ⁴ _{IX1}	LDX ³ _{IX}	
F	BCLR7 ⁵ _{BTB}	BCLR7 ⁵ _{BSC}	BH ³ _{REL}	CLR ³ _{DIR}	CLRA ³ _{INH}	CLR ³ _{INH}	CLR ⁶ _{IX1}	CLR ⁵ _{IX}	WAIT ² _{INH}		STX ² _{MM}	STX ³ _{DIR}	STX ⁴ _{EXT}	STX ⁵ _{IX2}	STX ⁴ _{IX1}	STX ³ _{IX}	
1111																	



Legend

- IX Indexed (no offset)
- IX1 Indexed, 1 byte (6-bit) offset
- IX2 Indexed, 2 byte (16-bit) offset
- REL Relative
- A Accumulator
- IMM Immediate

Not implemented

Abbreviations for address modes and registers

9.3.4 Extended

In the extended addressing mode, the effective address of the argument is contained in the two bytes following the opcode byte. Instructions with extended addressing mode are capable of referencing arguments anywhere in memory with a single three-byte instruction. When using the Freescale assembler, the user need not specify whether an instruction uses direct or extended addressing. The assembler automatically selects the short form of the instruction.

$$\begin{aligned} EA &= (PC+1):(PC+2); PC \leftarrow PC+3 \\ \text{Address bus high} &\leftarrow (PC+1); \text{Address bus low} \leftarrow (PC+2) \end{aligned}$$

9.3.5 Indexed, no offset

In the indexed, no offset addressing mode, the effective address of the argument is contained in the 8-bit index register. This addressing mode can access the first 256 memory locations. These instructions are only one byte long. This mode is often used to move a pointer through a table or to hold the address of a frequently referenced RAM or I/O location.

$$\begin{aligned} EA &= X; PC \leftarrow PC+1 \\ \text{Address bus high} &\leftarrow 0; \text{Address bus low} \leftarrow X \end{aligned}$$

9.3.6 Indexed, 8-bit offset

In the indexed, 8-bit offset addressing mode, the effective address is the sum of the contents of the unsigned 8-bit index register and the unsigned byte following the opcode. Therefore the operand can be located anywhere within the lowest 511 memory locations. This addressing mode is useful for selecting the *m*th element in an *n* element table.

$$\begin{aligned} EA &= X+(PC+1); PC \leftarrow PC+2 \\ \text{Address bus high} &\leftarrow K; \text{Address bus low} \leftarrow X+(PC+1) \\ \text{where } K &= \text{the carry from the addition of } X \text{ and } (PC+1) \end{aligned}$$

9.3.7 Indexed, 16-bit offset

In the indexed, 16-bit offset addressing mode, the effective address is the sum of the contents of the unsigned 8-bit index register and the two unsigned bytes following the opcode. This address mode can be used in a manner similar to indexed, 8-bit offset except that this three-byte instruction allows tables to be anywhere in memory. As with direct and extended addressing, the Freescale assembler determines the shortest form of indexed addressing.

$$\begin{aligned} EA &= X+[(PC+1):(PC+2)]; PC \leftarrow PC+3 \\ \text{Address bus high} &\leftarrow (PC+1)+K; \text{Address bus low} \leftarrow X+(PC+2) \\ \text{where } K &= \text{the carry from the addition of } X \text{ and } (PC+2) \end{aligned}$$

9.3.8 Relative

The relative addressing mode is only used in branch instructions. In relative addressing, the contents of the 8-bit signed byte (the offset) following the opcode are added to the PC if, and only if, the branch conditions are true. Otherwise, control proceeds to the next instruction. The span of relative addressing is from -126 to $+129$ from the opcode address. The programmer need not calculate the offset when using the Freescale assembler, since it calculates the proper offset and checks to see that it is within the span of the branch.

$$\begin{aligned} \text{EA} &= \text{PC}+2+(\text{PC}+1); \text{PC} \leftarrow \text{EA} \text{ if branch taken;} \\ &\text{otherwise EA} = \text{PC} \leftarrow \text{PC}+2 \end{aligned}$$

9.3.9 Bit set/clear

In the bit set/clear addressing mode, the bit to be set or cleared is part of the opcode. The byte following the opcode specifies the address of the byte in which the specified bit is to be set or cleared. Any read/write bit in the first 256 locations of memory, including I/O, can be selectively set or cleared with a single two-byte instruction.

$$\begin{aligned} \text{EA} &= (\text{PC}+1); \text{PC} \leftarrow \text{PC}+2 \\ \text{Address bus high} &\leftarrow 0; \text{Address bus low} \leftarrow (\text{PC}+1) \end{aligned}$$

9.3.10 Bit test and branch

The bit test and branch addressing mode is a combination of direct addressing and relative addressing. The bit to be tested and its condition (set or clear) is included in the opcode. The address of the byte to be tested is in the single byte immediately following the opcode byte (EA1). The signed relative 8-bit offset in the third byte (EA2) is added to the PC if the specified bit is set or cleared in the specified memory location. This single three-byte instruction allows the program to branch based on the condition of any readable bit in the first 256 locations of memory. The span of branch is from -125 to $+130$ from the opcode address. The state of the tested bit is also transferred to the carry bit of the condition code register.

$$\begin{aligned} \text{EA1} &= (\text{PC}+1); \text{PC} \leftarrow \text{PC}+2 \\ \text{Address bus high} &\leftarrow 0; \text{Address bus low} \leftarrow (\text{PC}+1) \\ \text{EA2} &= \text{PC}+3+(\text{PC}+2); \text{PC} \leftarrow \text{EA2} \text{ if branch taken;} \\ &\text{otherwise PC} \leftarrow \text{PC}+3 \end{aligned}$$

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10

ELECTRICAL SPECIFICATIONS

This section contains the electrical specifications and associated timing information for the MC68HC05F4.

10.1 Maximum ratings

Table 10-1 Maximum ratings

Rating ⁽¹⁾	Symbol	Value	Unit
Supply voltage	V_{DD}	- 0.3 to + 0.7	V
Input voltage	V_{IN}	$V_{SS} - 0.3$ to $V_{SS} + 0.3$	V
Bootloader mode (IRQ pin only)	V_{IN}	$V_{SS} - 0.3$ to $2 \times V_{DD} + 0.3$	V
Current drain per pin ⁽²⁾ — excluding VDD and VSS	I	25	mA
Operating temperature range — standard — extended	T	T_L to T_H 0 to + 70 - 40 to + 85	°C
Storage temperature range	T_{STG}	- 65 to + 150	°C

(1) All voltages are with respect to V_{SS} .

(2) Maximum current drain per pin is for one pin at a time, limited by an external resistor.

Note: This device contains circuitry designed to protect against damage due to high electrostatic voltages or electric fields. However, it is recommended that normal precautions be taken to avoid the application of any voltages higher than those given in the Maximum Ratings table to this high impedance circuit. For maximum reliability all unused inputs should be tied to either V_{SS} or V_{DD} .

10.2 Thermal characteristics and power considerations

Table 10-2 Package thermal characteristics

Characteristics	Symbol	Value	Unit
Thermal resistance – 44-pin QFP package – 28-pin SOIC package – 28 pin PDIP package	θ_{JA}	60	$^{\circ}\text{C/W}$

The average chip junction temperature, T_J , in degrees Celsius can be obtained from the following equation:

$$T_J = T_A + (P_D \cdot \theta_{JA})$$

where:

T_A = Ambient Temperature ($^{\circ}\text{C}$)

θ_{JA} = Package Thermal Resistance,

Junction-to-ambient ($^{\circ}\text{C/W}$)

$P_D = P_{INT} + P_{I/O}$ (W)

P_{INT} = Internal Chip Power = $I_{DD} \cdot V_{DD}$ (W)

$P_{I/O}$ = Power Dissipation on Input and Output pins (User determined)

An approximate relationship between P_D and T_J (if $P_{I/O}$ is neglected) is:

$$P_D = \frac{K}{T_J + 273}$$

Solving equations [1] and [2] for K gives:

$$K = P_D \cdot (T_A + 273) + \theta_{JA} \cdot P_D^2$$

where K is a constant for a particular part. K can be determined by measuring P_D (at equilibrium) for a known T_A . Using this value of K, the values of P_D and T_J can be obtained for any value of T_A by solving the above equations. The package thermal characteristics are shown in [Table 10-2](#).

10.3 DC electrical characteristics

Table 10-3 DC electrical characteristics ($V_{DD} = 5.0\text{ V}$)

($V_{DD} = 5.0V_{DC} \pm 10\%$, $V_{SS} = 0\text{ V}_{DC}$, $T = -40^{\circ}\text{C}$ to 85°C , unless otherwise stated)

Characteristic	Symbol	Min.	Typ. ⁽¹⁾	Max.	Unit
Output voltage $I_{LOAD} = -10\ \mu\text{A}$ $I_{LOAD} = +10\ \mu\text{A}$	V_{OH} V_{OL}	$V_{DD} - 0.1$ —	— —	— 0.1	V V
Output high voltage ($I_{LOAD} = -0.8\text{ mA}$) Ports (PA0–7, PB2–7, PC0–7)	V_{OH}	$V_{DD} - 0.8$	—	—	V
Output low voltage ($I_{LOAD} = +1.6\text{ mA}$) Ports (PA0–7, PB0–7, PC0–7, PD0–7) TCMP1–2	V_{OL}	—	—	0.4	V
Input high voltage Ports (PA0–7, PB0–7, PC0–7, PD0–7) $\overline{\text{IRQ}}$, $\overline{\text{RESET}}$, OSC1, TCAP1–2	V_{IH}	$0.7V_{DD}$	—	V_{DD}	V
Input low voltage Ports (PA0–7, PB0–7, PC0–7, PD0–7) $\overline{\text{IRQ}}$, $\overline{\text{RESET}}$, OSC1, TCAP1–2	V_{IL}	V_{SS}	—	$0.2V_{DD}$	V
Supply Current ⁽²⁾ RUN WAIT STOP	I_{DD}	— — —	2.5 0.8 —	5 1.2 80	mA mA μA
I/O ports hi-Z leakage current Ports (PA0–7, PB0–7, PC0–7, PD0–7)	I_{OZ}	—	—	10	μA
Input current $\overline{\text{RESET}}$, $\overline{\text{IRQ}}$, OSC1, TCAP1–2	I_{IN}	—	—	1	μA
Capacitance Ports (as input or output) $\overline{\text{RESET}}$, $\overline{\text{IRQ}}$	C_{OUT} C_{IN}	— —	— —	12 8	pF pF
Input current low, $V_{IN} = 0\text{ V}$ Ports (PA0–7, PB2–3, PC0–7), $\overline{\text{RESET}}$	I_{IL}	–30	–90	–170	μA
Input current high, $V_{IN} = V_{DD}$ PB4–7	I_{IH}	30	90	170	μA

(1) Typical values are at midpoint of voltage range and at 25°C only.

(2) All I_{DD} measurements taken with suitable decoupling capacitors across the power supply to suppress the transient switching currents inherent in CMOS designs. RUN and WAIT I_{DD} : measured using an external square-wave clock source ($f_{OSC} = 3.58\text{ MHz}$); all inputs 0.2 V from rail; no DC loads; maximum load on outputs 50 pF (20 pF on OSC2). WAIT I_{DD} : only the timer system and DMG active; current varies linearly with the OSC2 capacitance. STOP and WAIT I_{DD} : all ports configured as inputs, $V_{IL} = 0.2\text{ V}$, $V_{IH} = V_{DD} - 0.2\text{ V}$. STOP I_{DD} : measured with $OSC1 = V_{SS}$.

Table 10-4 DC electrical characteristics ($V_{DD} = 2.7\text{ V}$)

($V_{DD} = 2.7\text{ V}_{DC\text{ min}}$, $V_{SS} = 0\text{ V}_{DC}$, $T = -40^{\circ}\text{C}$ to 85°C , unless otherwise stated)

Characteristic	Symbol	Min.	Typ. ⁽¹⁾	Max.	Unit
Output voltage $I_{LOAD} = -10\ \mu\text{A}$ $I_{LOAD} = +10\ \mu\text{A}$	V_{OH} V_{OL}	$V_{DD} - 0.1$ —	— —	— 0.1	V V
Output high voltage ($I_{LOAD} = -0.2\text{ mA}$) Ports (PA0–7, PB2–7, PC0–7)	V_{OH}	$V_{DD} - 0.3$	—	—	V
Output low voltage ($I_{LOAD} = +0.4\text{ mA}$) Ports (PA0–7, PB0–7, PC0–7, PD0–7) TCMP1–2	V_{OL}	—	—	0.3	V
Input high voltage Ports (PA0–7, PB0–7, PC0–7, PD0–7) $\overline{\text{IRQ}}$, $\overline{\text{RESET}}$, OSC1, TCAP1–2	V_{IH}	$0.7V_{DD}$	—	V_{DD}	V
Input low voltage Ports (PA0–7, PB0–7, PC0–7, PD0–7) $\overline{\text{IRQ}}$, $\overline{\text{RESET}}$, OSC1, TCAP1–2	V_{IL}	V_{SS}	—	$0.2V_{DD}$	V
Supply Current ⁽²⁾ RUN WAIT STOP	I_{DD}	— — —	1.5 0.5 —	3.0 1.0 40	mA mA μA
I/O ports hi-Z leakage current Ports (PA0–7, PB0–7, PC0–7, PD0–7)	I_{OZ}	—	—	10	μA
Input current $\overline{\text{RESET}}$, $\overline{\text{IRQ}}$, OSC1, TCAP1–2	I_{IN}	—	—	1	μA
Capacitance Ports (as input or output) $\overline{\text{RESET}}$, $\overline{\text{IRQ}}$	C_{OUT} C_{IN}	— —	— —	12 8	pF pF
Input current low, $V_{IN} = 0\text{ V}$ Ports (PA0–7, PB2–3, PC0–7), $\overline{\text{RESET}}$	I_{IL}	–5	–15	–40	μA
Input current high, $V_{IN} = V_{DD}$ PB4–7	I_{IH}	5	15	40	μA

(1) Typical values are at midpoint of voltage range and at 25°C only.

(2) All I_{DD} measurements taken with suitable decoupling capacitors across the power supply to suppress the transient switching currents inherent in CMOS designs. RUN and WAIT I_{DD} : measured using an external square-wave clock source ($f_{OSC} = 3.58\text{ MHz}$); all inputs 0.2 V from rail; no DC loads; maximum load on outputs 50 pF (20 pF on OSC2). WAIT I_{DD} : only the timer system and DMG active; current varies linearly with the OSC2 capacitance. STOP and WAIT I_{DD} : all ports configured as inputs, $V_{IL} = 0.2\text{ V}$, $V_{IH} = V_{DD} - 0.2\text{ V}$. STOP I_{DD} : measured with $\text{OSC1} = V_{SS}$.

Caution: There is a restriction on the use of indexed addressing for EEPROM read operations. When the base address of an indexed read of an EEPROM location is within the EEPROM address range ($\$0400$ to $\$04FF$), the read may not be successful. e.g. LDA (BASE ADDRESS), X – may not give the correct result when the base address is in the range $\$0400$ to $\$04FF$. However, if the base address is outwith the EEPROM address range, the read operation will be successful. This restriction applies to all operations capable of using indexed addressing.

10.4 Control timing

Table 10-5 Control timing ($V_{DD} = 5V$)

($V_{DD} = 5.0 V_{DC} \pm 10\%$, $V_{SS} = 0 V_{DC}$, $T = T_L$ to T_H)

Characteristic	Symbol	Min.	Max.	Unit
Frequency of operation:				
Crystal	f_{OSC}	—	3.579	MHz
External clock		DC	3.579	
Internal operating frequency:				
Crystal	f_{OP}	—	1.789	MHz
External clock		DC	1.789	
Processor cycle time	t_{CYC}	559.0	—	ns
Stop recovery start-up time	t_{ILCH}	—	20	ms
Crystal oscillator start-up time	t_{OXOV}	—	20.0	ms
RESET pulse width	t_{RL}	1.5	—	t_{CYC}
Interrupt pulse width low (edge-triggered)	t_{LIH}	250.0	—	ns
Interrupt pulse period	t_{LIL}	(1)	—	t_{CYC}
OSC1 pulse width	t_{OH}, t_{OL}	100.0	—	ns
EEPROM byte programming time	t_{EPGM}	—	15.0	ms
EEPROM byte erase time	t_{EBYTE}	—	15.0	ms
EEPROM block erase time	t_{EBLOCK}	—	100.0	ms
EEPROM bulk erase time	t_{EBULK}	—	300.0	ms
EEPROM programming voltage fall time	t_{FPV}	—	10.0	μs
EEPROM minimum programming voltage	V_{CCMIN}	2.7	—	V

(1) The minimum period T_{LIL} should not be less than the number of cycle times it takes to execute the interrupt service routine plus 21 t_{CYC} .

Table 10-6 Control timing ($V_{DD} = 2.7V$)

($V_{DD} = 2.7 V_{DC}$ min, $V_{SS} = 0 V_{DC}$, $T = T_L$ to T_H)

Characteristic	Symbol	Min.	Max.	Unit
Frequency of operation:				
Crystal	f_{OSC}	—	3.579	MHz
External clock	f_{OSC}	DC	3.579	MHz
Internal operating frequency:				
Crystal	f_{OP}	—	1.789	MHz
External clock	f_{OP}	DC	1.789	MHz
Processor cycle time	t_{CYC}	559.0	—	ns
Crystal oscillator start-up time	t_{OXOV}	—	20.0	ms
Stop recovery start-up time	t_{ILCH}	—	20	ms
RESET pulse width	t_{RL}	1.5	—	TCYC
Interrupt pulse width low (edge-triggered)	t_{ILIH}	250.0	—	ns
Interrupt pulse period	t_{ILIL}	(1)	—	t_{CYC}
OSC1 pulse width	TOH, TOL	100.0	—	ns
EEPROM Byte Programming time	t_{EPGM}	—	15.0	ms
EEPROM Byte Erase time	t_{EBYTE}	—	15.0	ms
EEPROM Block Erase time	t_{EBLOCK}	—	100.0	ms
EEPROM Bulk Erase time	t_{EBULK}	—	300.0	ms
EEPROM Programming Voltage fall time	t_{FPV}	—	10.0	μs
EEPROM minimum programming voltage	V_{CCMIN}	2.7	—	V

(1) The minimum period T_{ILIL} should not be less than the number of cycle times it takes to execute the interrupt service routine plus $21 t_{CYC}$.

10.5 DC levels for low voltage RESET and LVI

Table 10-7 DC levels for low voltage reset and LVI

(T = -40°C to 85°C, unless otherwise stated)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Power-on reset voltage	V_{RON}	2.55	2.8	3.05	V
Power-off reset voltage	V_{ROFF}	2.45	2.7	2.95	V
Low voltage interrupt	V_{LVI}	2.75	3.0	3.25	V

10.6 Electrical specifications for DTMF/melody generator

Table 10-8 Sine wave tones at TNO

Characteristic	Min.	Typ.	Max.	Unit
Operating voltage	2.7	—	5.5	V
Tone output level:				
Low group – row	0.120	0.160	0.210	V_{rms}
High group – column	0.160	0.205	0.280	V_{rms}
Frequency deviation (DTMF)	-0.65	—	+0.65	%
Frequency deviation (Melody)	-1.5	—	+1.5	%
Tone output DC level	0.45	0.50	0.55	Vdd
High group pre-emphasis	1	2.15	3	dB
Total harmonic distortion	—	-25	—	dB

Table 10-9 Square wave tones at TNO

Characteristic	Min.	Typ.	Max.	Unit
Operating voltage	2.7	—	5.5	V
Tone output level:				
Low group – row	—	0.270	—	V_{p-p}
High group – column	—	0.360	—	V_{p-p}
Frequency deviation (Melody)	-1.5	—	+1.5	%
Tone output DC level (+ 1/2 V_{p-p} value)	0.45	0.50	0.55	Vdd

Table 10-10 TONEX at TNX output

Characteristic	Min.	Typ.	Max.	Unit
Operating voltage	2.7	—	5.5	V
Tone output level (square wave)	—	V_{DD}	—	V_{p-p}
Frequency deviation	- 1.5	—	+ 1.5	%

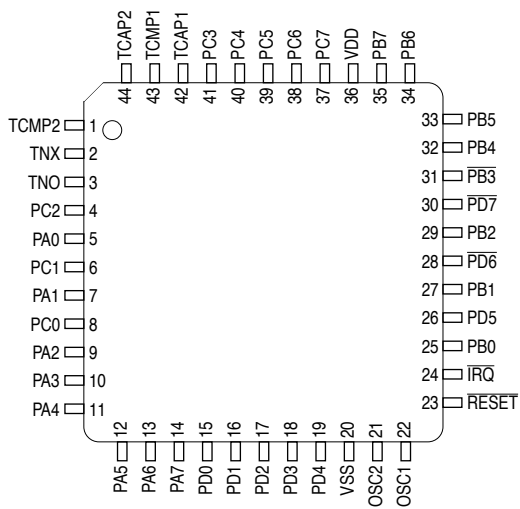
10.7 EEPROM additional information

Table 10-11 EEPROM additional information

Temperature	Read/write cycles	Remarks
0 °C – 85 °C	10 000	The value is regularly tested and monitored
50 °C	35 000	This value is predicted from the tested ones
25 °C	100 000	This value is predicted from the tested ones

11

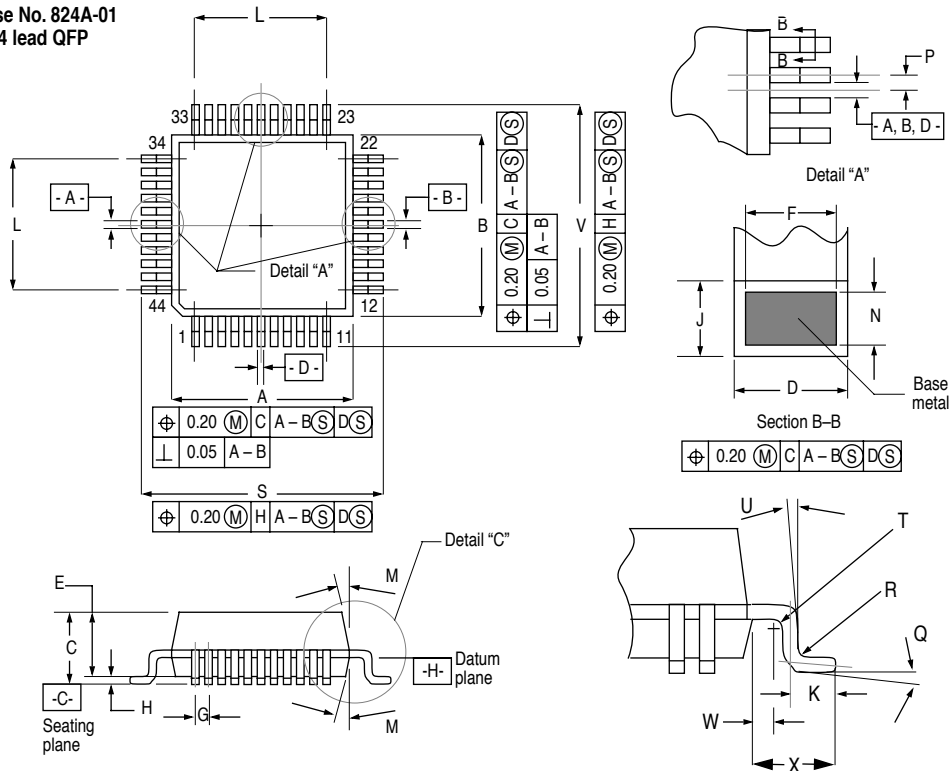
MECHANICAL DATA



11

Figure 11-1 44-pin QFP pinout

Case No. 824A-01
44 lead QFP



Dim.	Min.	Max.	Notes	Dim.	Min.	Max.
A	9.90	10.10	<ol style="list-style-type: none"> Datum plane –H– is located at bottom of lead and is coincident with the lead where the lead exits the plastic body at the bottom of the parting line. Datums A–B and –D– to be determined at datum plane –H–. Dimensions S and V to be determined at seating plane –C–. Dimensions A and B do not include mould protrusion. Allowable mould protrusion is 0.25mm per side. Dimensions A and B do include mould mismatch and are determined at datum plane –H–. Dimension D does not include dambar protrusion. Allowable dambar protrusion shall be 0.08 total in excess of the D dimension at maximum material condition. Dambar cannot be located on the lower radius or the foot. Dimensions and tolerancing per ANSI Y 14.5M, 1982. All dimensions in mm. 	M	5°	10°
B	9.90	10.10		N	0.130	0.170
C	2.10	2.45		Q	0°	7°
D	0.30	0.45		R	0.13	0.30
E	2.00	2.10		S	12.95	13.45
F	0.30	0.40		T	0.13	—
G	0.80	BSC		U	0°	—
H	—	0.250		V	12.95	13.45
J	0.130	0.230		W	0.40	—
K	0.65	0.95		X	1.6	REF
L	8.00	REF				

Figure 11-2 44-pin QFP mechanical dimensions

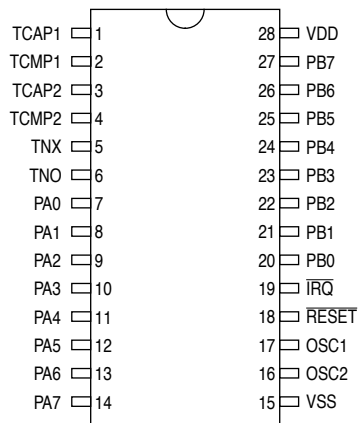
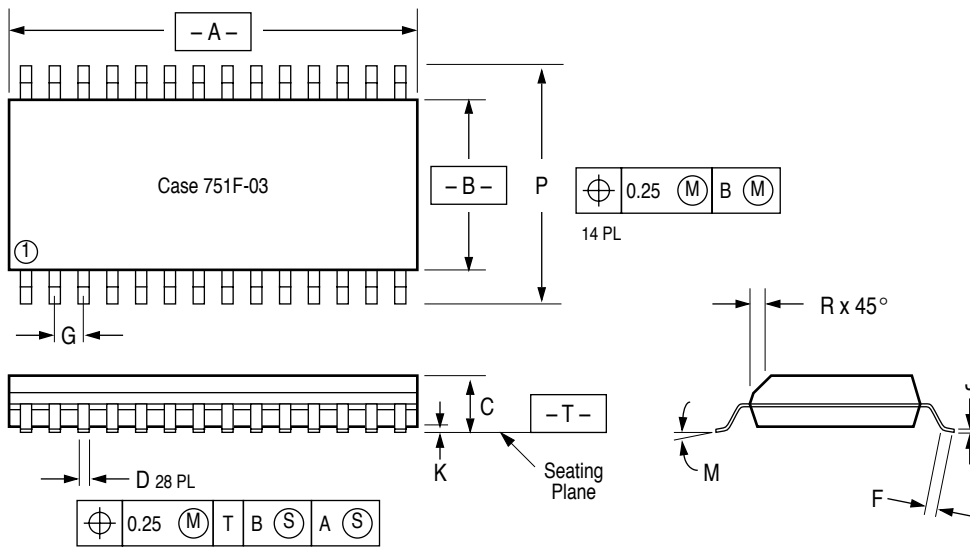


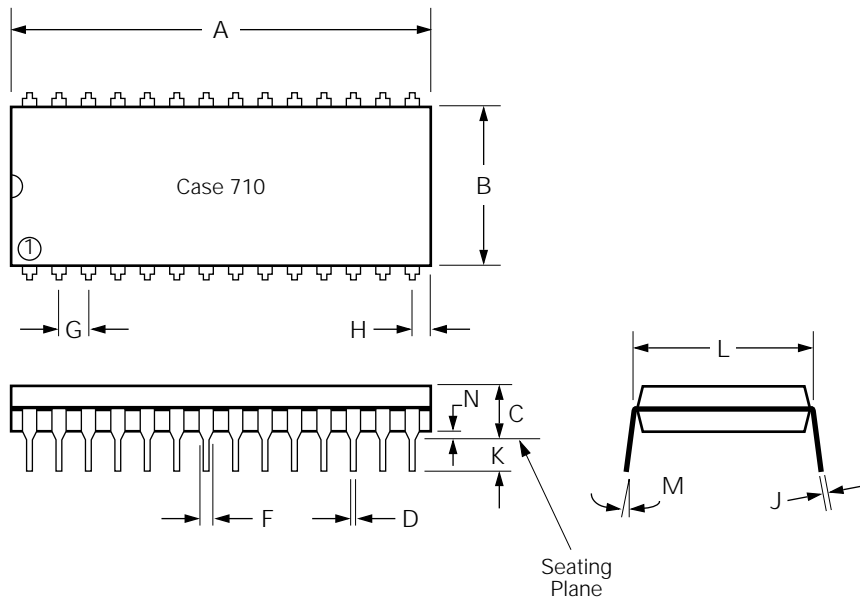
Figure 11-3 28-pin PDIP/SOIC pinout



Dim.	Min.	Max.	Notes	Dim.	Min.	Max.
A	17.80	18.05	1. Dimensions 'A' and 'B' are datums and 'T' is a datum surface. 2. Dimensioning and tolerancing per ANSI Y14.5M, 1982. 3. All dimensions in mm. 4. Dimensions 'A' and 'B' do not include mould protrusion. 5. Maximum mould protrusion is 0.15 mm per side.	J	0.229	0.317
B	7.40	7.60		K	0.127	0.292
C	2.35	2.65		M	0°	8°
D	0.35	0.49		P	10.05	10.55
F	0.41	0.90		R	0.25	0.75
G	1.27 BSC		-	-	-	-

Figure 11-4 28-pin SOIC mechanical dimensions

11



Dim.	Min.	Max.	Notes	Dim.	Min.	Max.
A	36.45	37.21	1. All dimensions in mm. 2. Positional tolerance of leads ('D') shall be within 0.25 mm at maximum material condition, in relation to seating plane and to each other. 3. Dimension 'L' is to centre of leads when formed parallel. 4. Dimension 'B' does not include mould protrusion.	H	1.65	2.16
B	13.72	14.22		J	0.20	0.38
C	3.94	5.08		K	2.92	3.43
D	0.36	0.56		L	15.24 BSC	
F	1.02	1.52		M	0°	15°
G	2.54 BSC			N	0.51	1.02

Figure 11-5 Mechanical dimensions for 28-pin PDIP package

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ORDERING INFORMATION

This section describes the information needed to order the MC68HC05F4.

To initiate a ROM pattern for the MCU, it is necessary to first contact your local field service office, local sales person or Freescale representative. Please note that you will need to supply details such as: mask option selections; temperature range; oscillator frequency; package type; electrical test requirements; and device marking details so that an order can be processed, and a customer specific part number allocated. Refer to [Table 12-1](#) for appropriate part numbers.

Table 12-1 MC order numbers

Device title	Package type	Temperature	Part number
MC68HC05F4	44-pin QFP	0 to 70 °C	MC68HC05F4FB
	28-pin SOIC		MC68HC05F4DW
	28-pin DIP		MC68HC05F4P
MC68HC05F4	44-pin QFP	-40 to 85 °C	MC68HC05F4CFB
	28-pin SOIC		MC68HC05F4CDW
	28-pin DIP		MC68HC05F4CP
MC68HC705F4	44-pin QFP	0 to 70 °C	MC68HC705F4FB
	28-pin SOIC		MC68HC705F4DW
	28-pin DIP		MC68HC705F4P

12

12.1 EPROMs

For the MC68HC05F4, a 16K byte EPROM programmed with the customer's software (positive logic for address and data) should be submitted for pattern generation. All unused bytes should be programmed to \$00. The EPROM should be clearly labelled, placed in a conductive IC carrier and securely packed.

12.2 Verification media

All original pattern media (EPROMs) are filed for contractual purposes and are not returned. A computer listing of the ROM code will be generated and returned with a listing verification form. The listing should be thoroughly checked and the verification form completed, signed and returned to Freescale. The signed verification form constitutes the contractual agreement for creation of the custom mask. If desired, Freescale will program blank EPROMs (supplied by the customer) from the data file used to create the custom mask, to aid in the verification process.

12.3 ROM verification units(RVU)

Ten MCUs containing the customer's ROM pattern will be provided for program verification. These units will have been made using the custom mask but are for ROM verification only. For expediency, they are usually unmarked and are tested only at room temperature (25°C) and at 5 Volts. These RVUs are included in the mask charge and are not production parts. They are neither backed nor guaranteed by Freescale Quality Assurance.

A

FEATURES SPECIFIC TO THE MC68HC705F4

The MC68HC705F4 is the EPROM version of the MC68HC05F4, having 7679 bytes of EPROM plus 367 bytes of bootloader ROM. It has the same amount of RAM, EEPROM, I/O, and user vectors. It also has the same on-board peripherals as the MC68HC05F4.

A.1 Features

- 7680 bytes of user EPROM plus 16 bytes of user vectors
- 368 bytes of bootloader ROM
- Available in 44-pin QFP package, 28-pin SOIC package and 28-pin PDIP package (ports C and D not available in 28-pin packages)

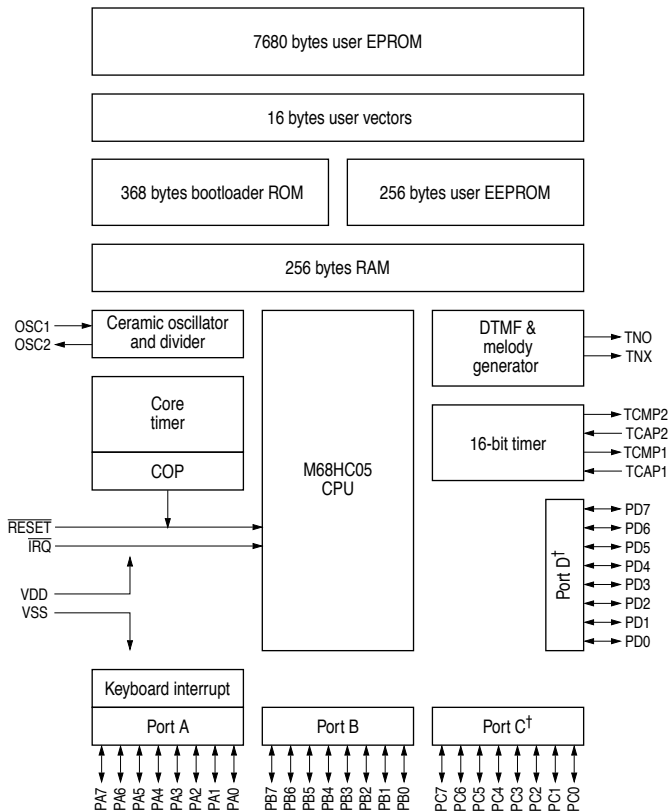
A.2 Memory and registers

The MC68HC705F4 has a 16K byte memory map consisting of registers (for I/O, control and status), user RAM, user ROM, EEPROM, bootloader ROM and reset and interrupt vectors as shown in [Figure A-2](#).

A

A.2.1 Registers

All the I/O, control and status registers of the MC68HC705F4 are contained within the first 64 byte block of the memory map, as detailed in [Table A-1](#).



† Note that ports C and D are only available with the 44-pin package.

A

Figure A-1 MC68HC705F4 block diagram

MC68HC705F4

\$0000	I/O (64 bytes)	\$00 Port A data (PORTA)
		\$01 Port B data (PORTB)
		\$02 Port C data ¹ (PORTC)
		\$03 Port D data ¹ (PORTD)
\$0040	RAM (384 bytes)	\$04 Port A DDR (DDRA)
		\$05 Port B DDR (DDRB)
		\$06 Port C DDR ¹ (DDRC)
		\$07 Port D DDR ¹ (DDRD)
\$00C0	Stack ↑	\$08 Core time control/status (CTCSR)
\$00FF		\$09 Core timer counter (CTCR)
\$0140	Unused	\$0A Unused
\$0200	EEPROM (256 bytes)	\$0B Reserved
		\$0C Reserved
\$02FF	Unused	\$0D DTMF row frequency counter (FCR)
		\$0E DTMF column frequency counter (FCC)
		\$0F DTMF tone control (TNCR)
\$3000	User EPROM (7680 bytes)	\$10 Key control (KCR)
		\$11 System options (SOR)
		\$12-\$1B Unused
		\$1C EEPROM programming (EEPROG)
		\$1D EPROM programming (EPROG)
		\$1E Unused
		\$1F Reserved
		\$20 Capture 1 high (ICR1H)
		\$21 Capture 1 low (ICR1L)
\$3F00	Bootloader ROM (368 bytes)	\$22 Compare 1 high (OCR1H)
		\$23 Compare 1 low (OCR1L)
		\$24 Capture 2 high (ICR2H)
		\$25 Capture 2 low (ICR2L)
\$3FF0	User vectors (16 bytes)	\$26 Compare 2 high (OCR2H)
		\$27 Compare 2 low (OCR2L)
\$3FFF		\$28 Timer counter high (CNTH)
		\$29 Timer counter low (CNTL)
		\$2A Alternate counter high (ACNTH)
		\$2B Alternate counter low (ACNTL)
		\$2C Timer control 1 (TCR1)
		\$2D Timer control 2 (TCR2)
		\$2E Timer status (TSR)
		\$2F-\$3F Unused

1. Not available in 28-pin package.

Figure A-2 MC68HC705F4 memory map

Table A-1 Register outline

Register Name	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Port A data (PORTA)	\$0000	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0	undefined
Port B data (PORTB)	\$0001	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0	undefined
Port C data (PORTC) ⁽¹⁾	\$0002	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0	undefined
Port D data (PORTD) ⁽¹⁾	\$0003	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0	undefined
Port A data direction (DDRA)	\$0004									0000 0000
Port B data direction (DDRB)	\$0005									0000 0000
Port C data direction (DDRC) ⁽¹⁾	\$0006									0000 0000
Port D data direction ((DDRD) ⁽¹⁾	\$0007									0000 0000
Core timer control/status (CTCSR)	\$0008	CTOF	RTIF	CTOFE	RTIE	RTOF	RRTIF	RT1	RT0	uu00 0011
Core timer counter (CTCR)	\$0009									0000 0000
DTMF row freq. control (FCR)	\$000D	0	0	0	FCR4	FCR3	FCR2	FCR1	FCR0	undefined
DTMF column freq. control (FCC)	\$000E	0	0	0	FCC4	FCC3	FCC2	FCC1	FCC0	undefined
DTMF tone control (TNCR)	\$000F	MS1	MS0	TGER	TGEC	TNOE	0	0	0	0000 0000
Key control (KCR)	\$0010	KF	KIE	0	0	0	0	0	0	0000 0000
System options (SOR)	\$0011	LVIF	LVIE	LVION	SC	IRQ	0	0	0	0000 0000
EEPROM programming (EPROG)	\$001C	0	CPEN	0	ER1	ER0	LATCH	EERC	EEPGM	0000 0000
EPROM programming (EPROG)	\$001D	0	0	0	TS1	TS0	ELATCH	0	EPGM	0000 0000
Input capture 1 high (ICR1H)	\$0020	(bit 15)							(bit 8)	undefined
Input capture 1 low (ICR1L)	\$0021									undefined
Output compare 1 high (OCR1H)	\$0022	(bit 15)							(bit 8)	undefined
Output compare 1 low (OCR1L)	\$0023									undefined
Input capture 2 high (ICR2H)	\$0024	(bit 15)							(bit 8)	undefined
Input capture 2 low (ICR2L)	\$0025									undefined
Output compare 2 high (OCR2H)	\$0026	(bit 15)							(bit 8)	undefined
Output compare 2 low (OCR2L)	\$0027									undefined

A

Table A-1 Register outline

Register Name	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Timer counter high (CNTH)	\$0028	(bit 15)							(bit 8)	1111 1111
Timer counter low (CNTL)	\$0029									1111 1100
Alternate counter high (ACNTH)	\$002A	(bit 15)							(bit 8)	1111 1111
Alternate counter low (ACNTL)	\$002B									1111 1100
Timer control 1 (TCR1)	\$002C	IC1E	IC2E	OC1E	TOIE	CO1E	IEDG1	IEDG2	OLVL1	0000 0uu0
Timer control 2 (TCR2)	\$002D	0	0	OC2E	0	CO2E	0	0	OLVL2	0000 0000
Timer status (TSR)	\$002E	IC1F	IC2F	OC1F	TOF	TCAP1	TCAP2	OC2F	0	uuuu uu00

u = undefined

(1) Not available in 28-pin packages

A.2.2 EPROM

The MC68HC705F4 has 7680 bytes of EPROM located from \$2000 to \$3DFF, plus 16 bytes of user vectors from \$3FF0 to \$3FFF. Up to 4 bytes of EPROM can be programmed simultaneously by correctly manipulating the bits in the EPROM programming register.

A.2.2.1 EPROM programming register (PROG)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
EPROM programming (PROG)	\$001D	0	0	0	0	0	ELATCH	0	EPGM	0000 0000

EPGM — EPROM program control

- 1 (set) — Programming power connected to the EPROM array.
- 0 (clear) — Programming power disconnected from the EPROM array.

ELATCH and EPGM cannot be set on the same write operation. EPGM can only be set if ELATCH is set. EPGM is automatically cleared when ELATCH is cleared.

ELATCH — EPROM latch control

- 1 (set) — EPROM address and data buses configured for programming.
- 0 (clear) — EPROM address and data buses configured for normal reads



ELATCH causes address and data buses to be latched when a write to EPROM is carried out. The EPROM cannot be read if ELATCH = 1. This bit should not be set unless a programming voltage is applied to the VPP pin.

A.2.2.2 EPROM programming operation

The following steps should be taken to program a byte of EPROM:

- 1) Apply the programming voltage V_{PP} to the \overline{IRQ} pin.
- 2) Set the ELATCH bit.
- 3) Write to the EPROM address.
- 4) Set the EPGM bit for a time t_{EPGM} to apply the programming voltage.
- 5) Clear the ELATCH bit.

If the address bits A13–A2 do not change, i.e. all bytes are located within the same 4 byte address block, then multibyte programming is permitted. The multibyte programming facility allows up to 4bytes of data to be written to the desired addresses after the ELATCH bit has been set.

A.3 Electrical specifications

This section gives the electrical specifications for the MC68HC705F4, the EPROM version of the MC68HC05F4. Contained in this section is the information specific to the MC68HC705F4 which differs from that detailed in [Section 10](#).

A.3.1 EPROM characteristics

Table A-2 EPROM characteristics

Characteristic	Symbol	Value	Unit
EPROM programming voltage rate	V_{PP}	$V_{SS} - 0.3$ to $+17 + 0.5$	V
EPROM programming voltage	V_{PP}	typ. 16.0 min. 15.5 – max. 16.5	V
EPROM programming time	t_{EPGM}	min. 4.0	ms

A

GLOSSARY

This section contains abbreviations and specialist words used in this data sheet and throughout the industry. Further information on many of the terms may be gleaned from Freescale's ***M68HC11 Reference Manual, M68HC11RM/AD***, or from a variety of standard electronics text books.

\$xxxx	The digits following the '\$' are in hexadecimal format.
%xxxx	The digits following the '%' are in binary format.
A/D, ADC	Analog-to-digital (converter).
Bootstrap mode	In this mode the device automatically loads its internal memory from an external source on reset and then allows this program to be executed.
Byte	Eight bits.
CCR	Condition codes register; an integral part of the CPU.
CERQUAD	A ceramic package type, principally used for EPROM and high temperature devices.
Clear	'0' — the logic zero state; the opposite of 'set'.
CMOS	Complementary metal oxide semiconductor. A semiconductor technology chosen for its low power consumption and good noise immunity.
COP	Computer operating properly. <i>aka</i> 'watchdog'. This circuit is used to detect device runaway and provide a means for restoring correct operation.
CPU	Central processing unit.
D/A, DAC	Digital-to-analog (converter).
EEPROM	Electrically erasable programmable read only memory. <i>aka</i> 'EEROM'.
EPROM	Erasable programmable read only memory. This type of memory requires exposure to ultra-violet wavelengths in order to erase previous data. <i>aka</i> 'PROM'.
ESD	Electrostatic discharge.
Expanded mode	In this mode the internal address and data bus lines are connected to external pins. This enables the device to be used in much more complex systems, where there is a need for external memory for example.

EVS	Evaluation system. One of the range of platforms provided by Freescale for evaluation and emulation of their devices.
HC MOS	High-density complementary metal oxide semiconductor. A semiconductor technology chosen for its low power consumption and good noise immunity.
I/O	Input/output; used to describe a bidirectional pin or function.
Input capture	(IC) This is a function provided by the timing system, whereby an external event is 'captured' by storing the value of a counter at the instant the event is detected.
Interrupt	This refers to an asynchronous external event and the handling of it by the MCU. The external event is detected by the MCU and causes a predetermined action to occur.
$\overline{\text{IRQ}}$	Interrupt request. The overline indicates that this is an active-low signal format.
K byte	A kilo-byte (of memory); 1024 bytes.
LCD	Liquid crystal display.
LSB	Least significant byte.
M68HC05	Freescale's family of 8-bit MCUs.
MCU	Microcontroller unit.
MI BUS	Freescale interconnect bus. A single wire, medium speed serial communications protocol.
MSB	Most significant byte.
Nibble	Half a byte; four bits.
NRZ	Non-return to zero.
Opcode	The opcode is a byte which identifies the particular instruction and operating mode to the CPU. See also: prebyte, operand.
Operand	The operand is a byte containing information the CPU needs to execute a particular instruction. There may be from 0 to 3 operands associated with an opcode. See also: opcode, prebyte.
Output compare	(OC) This is a function provided by the timing system, whereby an external event is generated when an internal counter value matches a predefined value.
PLCC	Plastic leaded chip carrier package.
PLL	Phase-locked loop circuit. This provides a method of frequency multiplication, to enable the use of a low frequency crystal in a high frequency circuit.
Prebyte	This byte is sometimes required to qualify an opcode, in order to fully specify a particular instruction. See also: opcode, operand.

Pull-down, pull-up	These terms refer to resistors, sometimes internal to the device, which are permanently connected to either ground or V_{DD} .
PWM	Pulse width modulation. This term is used to describe a technique where the width of the high and low periods of a waveform is varied, usually to enable a representation of an analog value.
QFP	Quad flat pack package.
RAM	Random access memory. Fast read and write, but contents are lost when the power is removed.
RFI	Radio frequency interference.
RTI	Real-time interrupt.
ROM	Read-only memory. This type of memory is programmed during device manufacture and cannot subsequently be altered.
RS-232C	A standard serial communications protocol.
SAR	Successive approximation register.
SCI	Serial communications interface.
Set	'1' — the logic one state; the opposite of 'clear'.
Silicon glen	An area in the central belt of Scotland, so called because of the concentration of semiconductor manufacturers and users found there.
Single chip mode	In this mode the device functions as a self contained unit, requiring only I/O devices to complete a system.
SPI	Serial peripheral interface.
Test mode	This mode is intended for factory testing.
TTL	Transistor-transistor logic.
UART	Universal asynchronous receiver transmitter.
VCO	Voltage controlled oscillator.
Watchdog	<i>see</i> 'COP'.
Wired-OR	A means of connecting outputs together such that the resulting composite output state is the logical OR of the state of the individual outputs.
Word	Two bytes; 16 bits.
<u>XIRQ</u>	Non-maskable interrupt request. The overline indicates that this has an active-low signal format.

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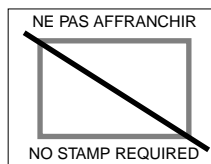


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